



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20120223003A
Add Cu as Alternative Bond Wire Metal for selected devices
Change Notification / Sample Request

Date: 12/4/2013
To: MOUSER PCN

Dear Customer:

The purpose of this version A is to retract devices from this change notification. The retraction is for select devices that were inadvertently included and are not affected by this change. We apologize for any inconvenience this may have caused.

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services
Phone: +1(214) 480-6037
Fax: +1(214) 480-6659

20120223003A
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TLC555IP	null
TLC555IPE4	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20120223003A	PCN Date:	12/04/2013
Title:	Add Cu as Alternative Bond Wire Metal for Select Devices		
Customer Contact:	PCN Manager	Phone:	+1(214)480-6037
		Dept:	Quality Services
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process
<input checked="" type="checkbox"/>		<input checked="" type="checkbox"/>	Assembly Materials
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification
<input type="checkbox"/>		<input type="checkbox"/>	Mechanical Specification
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling
<input type="checkbox"/>		<input type="checkbox"/>	Test Process
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process

PCN Details

Description of Change:

Revision A is to remove select devices in the Product Affected: 0.96 Mil Cu Bond Wire Option (with ~~strikerthrough~~) and highlighted in yellow. These devices were inadvertently added and not affected by this change.

Qualification of Cu bond wire option for select devices in the BGA, TSSOP, QFN, QFP and PDIP packages. See table below.

	Current Bond Wire (Au)	Additional Bond wire option (Cu)
Wire diameter (mils)	0.7, 0.8, 0.9, 0.96, 1.0, 1.15, 1.2, 1.31, 1.97, 1.98,	0.8, 0.96, 1.3, 2.0 Mil Dia.

① **The devices in the product Affected list (grouped by wire diameter) are being qualified by similarity. These package qualifications and devices in these package families have been covered in prior PCNs, primarily PCN 20101215001 and PCN 20110919000. The purpose of this PCN is to convert additional devices in the same package families to Cu wire.**

A summary of the Reference Qualifications are shown in the table below.

Reference Qualification #	Cu Wire Diameter / Pkg Type
1	0.8 mils / TSSOP
2	0.96 mils / TSSOP
3	1.3 mils/ TSSOP
4	2.0 mils / TSSOP
5	0.8 mils / QFP
6	0.96 mils / QFP
7	0.8 mils / QFN
8	0.96 mils / QFN
9	1.3 mils / QFN
10	2.0 mils / QFN
11	0.8 mils / BGA
12	0.96 mils / BGA
13	0.96 mils / PDIP

Reason for Change:			
1) To align with world technology trends and use wiring with enhanced mechanical and electrical properties.			
2) Maximize flexibility within our Assembly/Test production sites.			
3) Cu is easier to obtain and stock.			
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):			
This change is not expected to have any negative impact on the form, fit, function or reliability of the package.			
Changes to product identification resulting from this PCN:			
None.			
Product Affected: 0.8 Mil Cu Bond Wire Option			
74ALVC164245GRDR	SN74ALVC16244AZRDR	SN74LV4320AGKFR	SN74LVTH162373KR
74ALVC164245ZQLR	SN74ALVC164245KR	SN74LV4320AZKFR	SN74LVTH162374KR
74ALVC164245ZRDR	SN74ALVC16834ZQLR	SN74LV574AZQNR	SN74LVTH16244AGQLR
74ALVCH162373ZQLR	SN74ALVCH162373KR	SN74LVC139AZQNR	SN74LVTH16244AGRDR
74ALVCH16244GRDR	SN74ALVCH16244KR	SN74LVC162244AGQLR	SN74LVTH16244AZQLR
74ALVCH16244ZQLR	SN74ALVCH16245KR	SN74LVC162244AGRDR	SN74LVTH16244AZRDR
74ALVCH16244ZRDR	SN74ALVCH16373KR	SN74LVC162244AZQLR	SN74LVTH16245AGQLR
74ALVCH16245ZRDR	SN74ALVCH16374KR	SN74LVC16244AGQLR	SN74LVTH16245AGRDR
74ALVCH16373GRDR	SN74ALVCH16501KR	SN74LVC16244AGRDR	SN74LVTH16245AZQLR
74ALVCH16373ZQLR	SN74ALVCH32244KR	SN74LVC16244AZQLR	SN74LVTH16245AZRDR
74ALVCH16373ZRDR	SN74ALVCH32245KR	SN74LVC16244AZRDR	SN74LVTH16373GQLR
74ALVCH16374ZQLR	SN74ALVCH32374KR	SN74LVC16245AGQLR	SN74LVTH16373GRDR
74ALVCH16501ZQLR	SN74ALVCH32501KR	SN74LVC16245AGRDR	SN74LVTH16373ZQLR
74ALVCH32244ZKER	SN74ALVCH32973KR	SN74LVC16245AZQLR	SN74LVTH16373ZRDR
74ALVCH32245ZKER	SN74ALVCH373ZQNR	SN74LVC16245AZRDR	SN74LVTH16374GQLR
74ALVCH32374ZKER	SN74ALVTH16245KR	SN74LVC16373AGQLR	SN74LVTH16374GRDR
74ALVCH32501ZKFR	SN74ALVTH16373KR	SN74LVC16373AZQLR	SN74LVTH16500GQLR
74ALVCH32973ZKER	SN74ALVTH16374KR	SN74LVC16373AZRDR	SN74LVTH322374KR
74ALVCHR16245ZQLR	SN74ALVTH32244KR	SN74LVC16374AGRDR	SN74LVTH32244GKER
74ALVTH16244ZQLR	SN74ALVTH32373KR	SN74LVC16374AZQLR	SN74LVTH32244ZKER
74ALVTH16245ZQLR	SN74ALVTH32374KR	SN74LVC16374AZRDR	SN74LVTH32245GKER
74ALVTH16373ZQLR	SN74ALVTHR16245KR	SN74LVC32244GKER	SN74LVTH32245ZKER
74ALVTH16374ZQLR	SN74AUC16244GQLR	SN74LVC32244ZKER	SN74LVTH32373GKER
74ALVTH32244ZKER	SN74AUC16244ZQLR	SN74LVC32245GKER	SN74LVTH32373ZKER
74ALVTH32373ZKER	SN74AUC16245GQLR	SN74LVC32245ZKER	SN74LVTH32374GKER
74ALVTH32374ZKER	SN74AUC16245ZQLR	SN74LVC32373AGKER	SN74LVTH32374ZKER
74ALVTHR16245ZQLR	SN74AUC16373GQLR	SN74LVC32373AZKER	SN74VMEH22501AGQLR
74AVC16T245ZQLR-P	SN74AUC16373ZQLR	SN74LVC32374AGKER	SN74VMEH22501AZQLR
74AVCA164245ZQLR	SN74AUC245ZQNR	SN74LVC32374AZKER	SN74VMEH22501GQLR
74AVCAH164245ZQLR	SN74AUC32244GKER	SN74LVC373AGQNR	SN74VMEH22501ZQLR
74AVCB164245GRDR	SN74AUC32244ZKER	SN74LVC373AZQNR	TAS5534DGG
74AVCB164245ZQLR	SN74AUC32245GKER	SN74LVC573AGQNR	TAS5534DGG
74AVCB164245ZRDR	SN74AUC32245ZKER	SN74LVC573AZQNR	TAS5538DGG
74AVCB324245ZKER	SN74AUC32374GKER	SN74LVC574AZQNR	TAS5538DGG
74AVCBH164245ZQLR	SN74AUC32374ZKER	SN74LVCH16244AGQLR	TAS5701PAP-P
74AVCBH324245ZKER	SN74AUCH16244GQLR	SN74LVCH16244AGRDR	TAS5701PAP-PG4
74AVCH16T245ZQLR	SN74AUCH16244ZQLR	SN74LVCH16244AZQLR	TAS5704PAP-P
74LVCH322244AZKER	SN74AUCH16374GQLR	SN74LVCH16244AZRDR	TAS5704PAP-PG4
74LVCHR16245AGRDR	SN74AUCH16374ZQLR	SN74LVCH16245AGQLR	TAS5706PAP-P
74LVCHR16245AZQLR	SN74AUCH32244GKER	SN74LVCH16245AGRDR	TCA6404ZXUR
74LVCHR16245AZRDR	SN74AUCH32244ZKER	SN74LVCH16245AZRDR	TLV320AIC10IGQER
74LVCHR32245AZKER	SN74AUCH32374GKER	SN74LVCH16373AZQLR	TLV320AIC1103GQER
74LVCR162245ZQLR	SN74AUCH32374ZKER	SN74LVCH16373AZRDR	TLV320AIC1103ZQE
74LVTH162244GRDR	SN74AVC16244GQLR	SN74LVCH16374AGQLR	TLV320AIC1103ZQER

74LVTH162244ZQLR	SN74AVC16244ZQLR	SN74LVCH16374AZQLR	TLV320AIC1110GQER
74LVTH162244ZRDR	SN74AVC16373ZQLR	SN74LVCH16543AGQLR	TLV320AIC1110ZQER
74LVTH162245GRDR	SN74AVC16374GQLR	SN74LVCH322244AKR	TLV320AIC3012IRHBT
74LVTH162245ZQLR	SN74AVC16374ZQLR	SN74LVCH32244AGKER	TLV320AIC3016IRHBR
74LVTH162245ZRDR	SN74AVC16T245GQLR	SN74LVCH32244AZKER	TLV320AIC3016IRHBT
74LVTH162373ZQLR	SN74AVC16T245ZQLR	SN74LVCH32245AGKER	TLV320DAC33BNIZQCT
74LVTH162374ZQLR	SN74AVC20T245ZQLR	SN74LVCH32245AZKER	TLV320DAC33NIZQC
74LVTH162374ZRDR	SN74AVC32374GKER	SN74LVCH32373AGKER	UCD90120ARGCR
74LVTH322374ZKER	SN74AVCA164245KR	SN74LVCH32373AZKER	UCD90120ARGCT
AVC16T245ZQLR-D	SN74AVCAH164245KR	SN74LVCH32374AGKER	UCD90124ARGCR
AVC20T245ZQLR-D	SN74AVCB164245KR	SN74LVCH32374AZKER	UCD90124ARGCT
BQ500110RGZR	SN74AVCB324245KR	SN74LVCHR16245AKR	UCD90124NPFPC
BQ500110RGZT	SN74AVCBH164245KR	SN74LVCHR32245AKR	UCD90124NPFGR
BQ500210RGZR	SN74AVCBH324245KR	SN74LVCR162245KR	UCD90160RGCR
BQ500210RGZT	SN74CB3Q16211GQLR	SN74LVCR16245AZQLR	UCD90160RGCT
BQ500211RGZR	SN74CB3Q16211ZQLR	SN74LVCR2245AZQNR	UCD9090RGZR
BQ500211RGZT	SN74CB3Q32245GKER	SN74LVCR32245AGKER	UCD9090RGZT
BQ50050W100RGZR	SN74CB3Q32245ZKER	SN74LVCR32245AZKER	UCD90910-VRGCR
BQ50050W100RGZT	SN74CB3Q3244ZQNR	SN74LVCR32240AGKER	UCD90910-VRGCT
CBTLV16211CZRDR-P	SN74CB3Q3245GQNR	SN74LVCR32240AZKER	UCD9222RGZR
CDCE925R08PWR	SN74CB3Q3245ZQNR	SN74LVCR32244AGKER	UCD9222RGZT
CDCE949RGER	SN74CB3T16211GQLR	SN74LVCR32244AZKER	UCD9244NRGCR
CDCLVC1102PW	SN74CB3T16211ZQLR	SN74LVCR32245AGKER	UCD9244NRGCT
CDCLVC1102PWR	SN74CB3T16212ZQLR	SN74LVCR32245AZKER	UCD9244RGCR
CDCLVC1103PW	SN74CBT16211AZQLR	SN74LVT162244AGQLR	UCD9244RGCT
CDCLVC1103PWR	SN74CBT16212AZQLR	SN74LVT162244AGRDR	UCD9246ERGCR
CDCLVC1104PW	SN74CBT32245GKER	SN74LVT162244AZQLR	UCD9246ERGCT
CDCLVC1104PWR	SN74CBT32245ZKER	SN74LVT162244AZRDR	UCD9246FRGCR
CDCLVC1106PW	SN74CBT3245AZQNR	SN74LVT162245AGQLR	UCD9246FRGCT
CDCLVC1106PWR	SN74CBTK32245GKER	SN74LVT162245AZRDR	UCD9248EPFC
CDCLVC1108PW	SN74CBTK32245ZKER	SN74LVT16244BGQLR	UCD9248EPFGR
CDCLVC1108PWR	SN74GTL2033ZQLR	SN74LVT16244BZQLR	VSP5611RSHR
CDCLVC1110PW	SN74GTL2034ZQLR	SN74LVT16244BZRDR	VSP5612RSHR
CDCLVC1110PWR	SN74GTL22033ZQLR	SN74LVT16245BGQLR	VSP5620RSLR
CDCLVC1112PW	SN74GTL22034ZQLR	SN74LVT16245BGRDR	VSP5621RSLR
CDCLVC1112PWR	SN74GTLPH1645GQLR	SN74LVT16245BZQLR	VSP5622RSLR
DRV2603ZQVR	SN74GTLPH1645ZQLR	SN74LVT16245BZRDR	VSP6300AZSPR
DRV2603ZQVT	SN74GTLPH16927ZQLR	SN74LVT244BGQNR	VSP6300ZRCR
PCM3070IRHBT	SN74GTLPH3245GKFR	SN74LVT244BZQNR	VSP6300ZSPR
PDRV2603ZQVR	SN74GTLPH3245ZKFR	SN74LVT245BZQNR	VSP6826ZRCR
PVSP6244BZRDR	SN74GTLPH32912ZKFR	SN74LVT32244GKER	VSP8244AZRDR
SN74ALVC16244AGQLR	SN74GTLPH32916ZKFR	SN74LVT32244ZKER	VSP9800DAR
SN74ALVC16244AGRDR	SN74GTLPH32945KR	SN74LVTH162244KR	
SN74ALVC16244AZQLR	SN74GTLPH32945ZKER	SN74LVTH162245KR	

Product Affected: 0.96 Mil Cu Bond Wire Option			
74AC11000N	CD74HC4543E	SN74AHC8541N	SN74LV4052AN
74AC11000NE4	CD74HC4543EE4	SN74AHC8541N-P	SN74LV4052ANE4
74AC11004N	CD74HC533E	SN74AHC8541N-P2	SN74LV4053AN
74AC11004NE4	CD74HC533EE4	SN74AHC86N	SN74LV4053ANE4
74AC11008N	CD74HC534E	SN74AHC86NE4	SN74LV4066AN
74AC11008NE4	CD74HC534EE4	SN74AHCT00N	SN74LV4066ANE4
74AC11032N	CD74HC540E	SN74AHCT00NE4	SN74LV8144N-P
74AC11032NE4	CD74HC540EE4	SN74AHCT02N	SN74LV8144N-P2
74AC11074N	CD74HC541E	SN74AHCT02NE4	SN74LV81526AN-P
74AC11074NE4	CD74HC541EE4	SN74AHCT04N	SN74LV8153N
74AC11086N	CD74HC563E	SN74AHCT04NE4	SN74LV8153N-P
74AC11086NE4	CD74HC563EE4	SN74AHCT08N	SN74LV8153NE4
74AC11138N	CD74HC564E	SN74AHCT08NE4	SN74LV8153PW
74AC11138NE4	CD74HC564EE4	SN74AHCT123AN	SN74LV8153PWE4

74AC11257N	CD74HC573E	SN74AHCT123ANE4	SN74LV8153PWG4
74AC11257NE4	CD74HC573EE4	SN74AHCT125N	SN74LV8153PWR
74ACT11000N	CD74HC574E	SN74AHCT125NE4	SN74LV8153PWRE4
74ACT11000NE4	CD74HC574EE4	SN74AHCT126N	SN74LV8153PWRG4
74ACT11004N	CD74HC595E	SN74AHCT126NE4	SN74LV8154N
74ACT11004NE4	CD74HC595EE4	SN74AHCT132N	SN74LV8154N-P
74ACT11008N	CD74HC597E	SN74AHCT132NE4	SN74LV8154N-P2
74ACT11008NE4	CD74HC597EE4	SN74AHCT138N	SN74LV8154NE4
74ACT11030N	CD74HC640E	SN74AHCT138NE4	SN74LV8156N-P
74ACT11030NE4	CD74HC640EE4	SN74AHCT139N	SN74LV8158P-P
74ACT11032N	CD74HC670E	SN74AHCT139NE4	SN74LV8158P-P2
74ACT11032NE4	CD74HC670EE4	SN74AHCT14N	SN74LV8159N-P
74ACT11074N	CD74HC688E	SN74AHCT14NE4	SN74LV8159N-P2
74ACT11074NE4	CD74HC688EE4	SN74AHCT157N	SN74LV8160N-P
74AVC4T245RGYRG4	CD74HC7046AE	SN74AHCT157NE4	SN74LV8160N-P2
74AVCH4T245RGYRG4	CD74HC7046AEE4	SN74AHCT174N	SN74LV8161N-P
74CBTLV16292GR-P	CD74HC7266E	SN74AHCT174NE4	SN74LV8161N-P2
74CBTLV3257RGYRG4	CD74HC7266EE4	SN74AHCT240N	SN74LV8161PW-P
74LVCE161284DGGRE4	CD74HC73E	SN74AHCT240NE4	SN74LVC244AN
74LVCE161284DGGRG4	CD74HC73EE4	SN74AHCT244N	SN74LVC244ANE4
ADS1148IRHBR	CD74HC74E	SN74AHCT244NE4	SN74LVC244APWR
ADS1148IRHBT	CD74HC74EE4	SN74AHCT245N	SN74LVC244APWRE4
ADS1191IPBS	CD74HC75E	SN74AHCT245NE4	SN74LVC244APWRG4
ADS1191IPBSR	CD74HC75EE4	SN74AHCT273N	SN74LVC245AN
ADS1191IRSMR	CD74HC85E	SN74AHCT273NE4	SN74LVC245ANE4
ADS1191IRSMT	CD74HC85EE4	SN74AHCT32N	SN74LVC3G14P-P
ADS1192IPBS	CD74HC86E	SN74AHCT32NE4	SN74LVC3G14P-P2
ADS1192IPBSR	CD74HC86EE4	SN74AHCT373N	SN74LVC3G17P-P
ADS1192IRSMR	CD74HC93E	SN74AHCT373NE4	SN74LVC3G17P-P2
ADS1192IRSMT	CD74HC93EE4	SN74AHCT374N	SN74LVC86APW-P
ADS1194CPAG	CD74HCT00E	SN74AHCT374NE4	SN74LVCE161284DGGR
ADS1194CPAGR	CD74HCT00EE4	SN74AHCT540N	SN74LVCH245AZXYR
ADS1196CPAG	CD74HCT02E	SN74AHCT540NE4	SN74S00N
ADS1196CPAGR	CD74HCT02EE4	SN74AHCT541N	SN74S00NE4
ADS1198CPAG	CD74HCT03E	SN74AHCT541NE4	SN74S132N
ADS1198CPAGR	CD74HCT03EE4	SN74AHCT573N	SN74S132NE4
ADS1248IRHBR	CD74HCT04E	SN74AHCT573NE4	SN74S151N
ADS1248IRHBT	CD74HCT04EE4	SN74AHCT574N	SN74S151NE4
ADS1291IPBS	CD74HCT08E	SN74AHCT574NE4	SN74S157N
ADS1291IPBSR	CD74HCT08EE4	SN74AHCT594N	SN74S157NE4
ADS1291IRSMR	CD74HCT107E	SN74AHCT594NE4	SN74S174N
ADS1291IRSMT	CD74HCT107EE4	SN74AHCT595N	SN74S174NE4
ADS1292IPBS	CD74HCT109E	SN74AHCT595NE4	SN74S257N
ADS1292IPBSR	CD74HCT109EE4	SN74AHCT74N	SN74S257NE4
ADS1292IRSMR	CD74HCT10E	SN74AHCT74NE4	SN74S280N
ADS1292IRSMT	CD74HCT10EE4	SN74AHCT86N	SN74S280NE4
ADS1292RIPBS	CD74HCT112E	SN74AHCT86NE4	SN74S373N
ADS1292RIPBSR	CD74HCT112EE4	SN74AHCU04N	SN74S373NE4
ADS1294IPAG	CD74HCT11E	SN74AHCU04NE4	SN74S86N
ADS1294IPAGR	CD74HCT11EE4	SN74ALS1244AN	SN74S86NE4
ADS1296IPAG	CD74HCT123E	SN74ALS1244ANE4	SN75160BN
ADS1296IPAGR	CD74HCT123E-P	SN74ALS1245AN	SN75160BNE4
ADS1299CPAGR	CD74HCT123EE4	SN74ALS1245ANE4	SN75161BN
ADS7223SRHBR	CD74HCT125E	SN74ALS1645AN	SN75161BNE4
ADS7223SRHBT	CD74HCT125EE4	SN74ALS1645ANE4	SN75970B2DGG
ADS7852Y/250	CD74HCT126E	SN74ALS240A-1N	SN75970B2DGGG4
ADS7852Y/250G4	CD74HCT126EE4	SN74ALS240A-1NE4	SN75971B2DGG
ADS7852Y/2K	CD74HCT132E	SN74ALS240AN	SN75971B2DGGG4
ADS7852Y/2KG4	CD74HCT132EE4	SN74ALS240ANE4	SN75976A1DGG
ADS7852YB/250	CD74HCT137E	SN74ALS241CN	SN75976A1DGGG4

ADS7852YB/250G4	CD74HCT137EE4	SN74ALS241CNE4	SN75976A1DGGR
ADS7852YB/2K	CD74HCT138E	SN74ALS243AN	SN75976A1DGGRG4
ADS7852YB/2KG4	CD74HCT138EE4	SN74ALS243ANE4	SN75976A2DGG
ADS7862Y/250	CD74HCT139E	SN74ALS244C-1N	SN75976A2DGGG4
ADS7862Y/250G4	CD74HCT139EE4	SN74ALS244C-1NE4	SN75976A2DGGR
ADS7862Y/2K	CD74HCT147E	SN74ALS244CN	SN75976A2DGGRG4
ADS7862Y/2KG4	CD74HCT147EE4	SN74ALS244CNE4	SN75ALS160N
ADS7862YB/250	CD74HCT14E	SN74ALS245A-1N	SN75ALS160NE4
ADS7862YB/250G4	CD74HCT14EE4	SN74ALS245A-1NE4	SN75ALS161N
ADS7862YB/2K	CD74HCT151E	SN74ALS245AN	SN75ALS161NE4
ADS7862YB/2KG4	CD74HCT151EE4	SN74ALS245ANE4	SN75C1167N
ADS7864Y/250	CD74HCT153E	SN74ALS273N	SN75C1167NE4
ADS7864Y/250G4	CD74HCT153EE4	SN74ALS273NE4	SN75C1168N
ADS7864Y/2K	CD74HCT157E	SN74ALS299N	SN75C1168NE4
ADS7864Y/2KG4	CD74HCT157EE4	SN74ALS299NE4	SN75C23243DGGR
ADS7864YB/250	CD74HCT158E	SN74ALS30AN	SN75C23243DGGRE4
ADS7864YB/250G4	CD74HCT158EE4	SN74ALS30ANE4	SN75C23243DGGRG4
ADS7864YB/2K	CD74HCT161E	SN74ALS323N	SN75HVD05P
ADS7864YB/2KG4	CD74HCT161EE4	SN74ALS323NE4	SN75HVD05PE4
ADS7945SRTER	CD74HCT163E	SN74ALS33AN	SN75HVD06P
ADS7945SRTET	CD74HCT163EE4	SN74ALS33ANE4	SN75HVD06PE4
ADS7946SRTER	CD74HCT164E	SN74ALS373AN	SN75HVD07P
ADS7946SRTET	CD74HCT164EE4	SN74ALS373ANE4	SN75HVD07PE4
ADS7950SDBBT	CD74HCT165E	SN74ALS374AN	SN75HVD08P
ADS7950SDBBTG4	CD74HCT165EE4	SN74ALS374ANE4	SN75HVD08PE4
ADS7950SDBBTR	CD74HCT166E	SN74ALS518N	SN75HVD10P
ADS7950SDBBTRG4	CD74HCT166EE4	SN74ALS518NE4	SN75HVD10PE4
ADS7950SBRGER	CD74HCT173E	SN74ALS520N	SN75HVD12P
ADS7950SBRGET	CD74HCT173EE4	SN74ALS520NE4	SN75HVD12PE4
ADS7950SDBT	CD74HCT174E	SN74ALS521N	SN75LBC174AN
ADS7950SDBTG4	CD74HCT174EE4	SN74ALS521NE4	SN75LBC174ANE4
ADS7950SDBTR	CD74HCT175E	SN74ALS533AN	SN75LVCP412ARTJR
ADS7950SDBTRG4	CD74HCT175EE4	SN74ALS533ANE4	SN75LVCP412ARTJT
ADS7950SRGER	CD74HCT191E	SN74ALS534AN	SN75LVCP412RTJR
ADS7950SRGET	CD74HCT191EE4	SN74ALS534ANE4	SN75LVCP412RTJT
ADS7951SDBBT	CD74HCT193E	SN74ALS540-1N	SN75LVCP600SDSKR
ADS7951SDBBTG4	CD74HCT193EE4	SN74ALS540-1NE4	SN75LVCP600SDSKT
ADS7951SDBBTR	CD74HCT194E	SN74ALS540N	SNL8045DBT
ADS7951SDBBTRG4	CD74HCT194EE4	SN74ALS540NE4	TCA1116PWR
ADS7951SBRGER	CD74HCT20E	SN74ALS541-1N	TCA1116RTWR
ADS7951SBRGET	CD74HCT20EE4	SN74ALS541-1NE4	TCA6507RTER
ADS7951SDBT	CD74HCT21E	SN74ALS541N	TCA9554APWR
ADS7951SDBTG4	CD74HCT21EE4	SN74ALS541NE4	THS7327PHP
ADS7951SDBTR	CD74HCT221E	SN74ALS561AN	THS7327PHPG4
ADS7951SDBTRG4	CD74HCT221EE4	SN74ALS561ANE4	THS7327PHPR
ADS7951SRGER	CD74HCT237E	SN74ALS563BN	THS7327PHPRG4
ADS7951SRGET	CD74HCT237EE4	SN74ALS563BNE4	THS7347IPHP
ADS7952SDBBT	CD74HCT238E	SN74ALS564BN	THS7347IPHPG4
ADS7952SDBBTG4	CD74HCT238EE4	SN74ALS564BNE4	THS7347IPHPR
ADS7952SDBBTR	CD74HCT240E	SN74ALS569AN	THS7347IPHPRG4
ADS7952SDBBTRG4	CD74HCT240EE4	SN74ALS569ANE4	THS7364IPW
ADS7952SBRHBR	CD74HCT241E	SN74ALS573CN	THS7364IPWR
ADS7952SBRHBT	CD74HCT241EE4	SN74ALS573CNE4	THS7372IPW
ADS7952SDBT	CD74HCT243E	SN74ALS574BN	THS7372IPWR
ADS7952SDBTG4	CD74HCT243EE4	SN74ALS574BNE4	TL080CP
ADS7952SDBTR	CD74HCT244E	SN74ALS576BN	TL080CPE4
ADS7952SDBTRG4	CD74HCT244EE4	SN74ALS576BNE4	TL972IP
ADS7952SRHBR	CD74HCT245E	SN74ALS580BN	TL972IPE4
ADS7952SRHBT	CD74HCT245EE4	SN74ALS580BNE4	TL974IN
ADS7953SDBBT	CD74HCT251E	SN74ALS620AN	TL974INE4

ADS7953SDBBTG4	CD74HCT251EE4	SN74ALS620ANE4	TLC0820ACN
ADS7953SDBBTR	CD74HCT253E	SN74ALS621A-1N	TLC0820ACNE4
ADS7953SDBBTRG4	CD74HCT253EE4	SN74ALS621A-1NE4	TLC0820AIN
ADS7953SRHBR	CD74HCT257E	SN74ALS621AN	TLC0820AINE4
ADS7953SRHBHT	CD74HCT257EE4	SN74ALS621ANE4	TLC0831CP
ADS7953SDBT	CD74HCT258E	SN74ALS623AN	TLC0831CPE4
ADS7953SDBTG4	CD74HCT258EE4	SN74ALS623ANE4	TLC0831IP
ADS7953SDBTR	CD74HCT259E	SN74ALS638A-1N	TLC0831IPE4
ADS7953SDBTRG4	CD74HCT259EE4	SN74ALS638A-1NE4	TLC0832CP
ADS7953SRHBR	CD74HCT273E	SN74ALS638AN	TLC0832CPE4
ADS7953SRHBHT	CD74HCT273EE4	SN74ALS638ANE4	TLC0832IP
ADS8028IRTJR	CD74HCT27E	SN74ALS639AN	TLC0832IPE4
ADS8028IRTJT	CD74HCT27EE4	SN74ALS639ANE4	TLC0834CN
ADS8317IBDRBR	CD74HCT280E	SN74ALS640B-1N	TLC0834CNE4
ADS8317IBDRBT	CD74HCT280EE4	SN74ALS640B-1NE4	TLC0834IN
ADS8317IDRBR	CD74HCT283E	SN74ALS640BN	TLC0834INE4
ADS8317IDRBT	CD74HCT283EE4	SN74ALS640BNE4	TLC0838CN
ADS8322Y/250	CD74HCT297E	SN74ALS641A-1N	TLC0838CNE4
ADS8322Y/250G4	CD74HCT297EE4	SN74ALS641A-1NE4	TLC0838IN
ADS8322Y/2K	CD74HCT299E	SN74ALS641AN	TLC0838INE4
ADS8322Y/2KG4	CD74HCT299EE4	SN74ALS641ANE4	TLC083RGTR
ADS8322YB/250	CD74HCT30E	SN74ALS642A-1N	TLC083RGTT
ADS8322YB/250G4	CD74HCT30EE4	SN74ALS642A-1NE4	TLC1078CP
ADS8323Y/250	CD74HCT32E	SN74ALS645A-1N	TLC1078CPE4
ADS8323Y/250G4	CD74HCT32EE4	SN74ALS645A-1NE4	TLC1078IP
ADS8323Y/2K	CD74HCT354E	SN74ALS645AN	TLC1078IPE4
ADS8323Y/2KG4	CD74HCT354EE4	SN74ALS645ANE4	TLC1079CN
ADS8323YB/250	CD74HCT356E	SN74ALS679N	TLC1079CNE4
ADS8323YB/250G4	CD74HCT356EE4	SN74ALS679NE4	TLC1079IN
ADS8326IBDRBR	CD74HCT365E	SN74ALS688N	TLC1079INE4
ADS8326IBDRBT	CD74HCT365EE4	SN74ALS688NE4	TLC1541CN
ADS8326IDRBR	CD74HCT367E	SN74ALS760N	TLC1541CNE4
ADS8326IDRBT	CD74HCT367EE4	SN74ALS760NE4	TLC1541IN
ADS8327IBPW	CD74HCT368E	SN74ALS804AN	TLC1541INE4
ADS8327IBPWG4	CD74HCT368EE4	SN74ALS804ANE4	TLC1542CN
ADS8327IBPWR	CD74HCT373E	SN74ALS832AN	TLC1542CNE4
ADS8327IBPWRG4	CD74HCT373EE4	SN74ALS832ANE4	TLC1542IN
ADS8327IPW	CD74HCT374E	SN74ALS990N	TLC1542INE4
ADS8327IPWG4	CD74HCT374EE4	SN74ALS990NE4	TLC1543CN
ADS8327IPWR	CD74HCT377E	SN74ALVC245PW-P	TLC1543CNE4
ADS8327IPWRG4	CD74HCT377EE4	SN74AS10240AN	TLC1543IN
ADS8328IBPW	CD74HCT390E	SN74AS10240ANE4	TLC1543INE4
ADS8328IBPWG4	CD74HCT390EE4	SN74AS10244AN	TLC1549CP
ADS8328IBPWR	CD74HCT393E	SN74AS10244ANE4	TLC1549CPE4
ADS8328IBPWRG4	CD74HCT393EE4	SN74AS10245N	TLC1549IP
ADS8328IPW	CD74HCT40103E	SN74AS10245NE4	TLC1549IPE4
ADS8328IPWG4	CD74HCT40103EE4	SN74AS10640N	TLC2201CP
ADS8328IPWR	CD74HCT40105E	SN74AS10640NE4	TLC2201CPE4
ADS8328IPWRG4	CD74HCT40105EE4	SN74AS240AN	TLC2201IP
ADS8329IBPW	CD74HCT4020E	SN74AS240ANE4	TLC2201IPE4
ADS8329IBPWG4	CD74HCT4020EE4	SN74AS241AN	TLC2202CP
ADS8329IBPWR	CD74HCT4024E	SN74AS241ANE4	TLC2202CPE4
ADS8329IBPWRG4	CD74HCT4024EE4	SN74AS244AN	TLC2202IP
ADS8329IPW	CD74HCT4040E	SN74AS244ANE4	TLC2202IPE4
ADS8329IPWG4	CD74HCT4040EE4	SN74AS245N	TLC2274AIPW
ADS8329IPWR	CD74HCT4046AE	SN74AS245NE4	TLC251ACP
ADS8329IPWRG4	CD74HCT4046AEE4	SN74AS373N	TLC251ACPE4
ADS8330IBPW	CD74HCT4051E	SN74AS373NE4	TLC251BCP
ADS8330IBPWG4	CD74HCT4051EE4	SN74AS374N	TLC251BCPE4
ADS8330IBPWR	CD74HCT4052E	SN74AS374NE4	TLC251CP

ADS8330IBPWRG4	CD74HCT4052EE4	SN74AS533AN	TLC251CPE4
ADS8330IPW	CD74HCT4053E	SN74AS533ANE4	TLC252BCP
ADS8330IPWG4	CD74HCT4053EE4	SN74AS573AN	TLC252BCPE4
ADS8330IPWR	CD74HCT4060E	SN74AS573ANE4	TLC252CP
ADS8330IPWRG4	CD74HCT4060EE4	SN74AS574N	TLC252CPE4
ADS8331IBPW	CD74HCT4066E	SN74AS574NE4	TLC2543CN
ADS8331IBPWR	CD74HCT4066EE4	SN74AS576N	TLC2543CNE4
ADS8331IPW	CD74HCT4075E	SN74AS576NE4	TLC2543IN
ADS8331IPWR	CD74HCT4075EE4	SN74AS638AN	TLC2543INE4
ADS8332IBPW	CD74HCT4094E	SN74AS638ANE4	TLC254ACN
ADS8332IBPWR	CD74HCT4094EE4	SN74AS640N	TLC254ACNE4
ADS8332IPW	CD74HCT423E	SN74AS640NE4	TLC254BCN
ADS8332IPWR	CD74HCT423EE4	SN74AS641N	TLC254BCNE4
ADS8342IBPFBT	CD74HCT42E	SN74AS641NE4	TLC254CN
ADS8342IBPFBTG4	CD74HCT42EE4	SN74AS645N	TLC254CNE4
ADS8342IPFBT	CD74HCT4316E	SN74AS645NE4	TLC25L2BCP
ADS8342IPFBTG4	CD74HCT4316EE4	SN74AS756N	TLC25L2BCPE4
ADS8371IBPFBR	CD74HCT4351E	SN74AS756NE4	TLC25L2CP
ADS8371IBPFBRG4	CD74HCT4351EE4	SN74AS757N	TLC25L2CPE4
ADS8371IBPFBT	CD74HCT4511E	SN74AS757NE4	TLC25L4ACN
ADS8371IBPFBTG4	CD74HCT4511EE4	SN74AS760N	TLC25L4ACNE4
ADS8371IPFBT	CD74HCT4520E	SN74AS760NE4	TLC25L4BCN
ADS8371IPFBTG4	CD74HCT4520EE4	SN74AS804BN	TLC25L4BCNE4
ADS8381IBPFBT	CD74HCT4538E	SN74AS804BNE4	TLC25L4CN
ADS8381IBPFBTG4	CD74HCT4538EE4	SN74AS805BN	TLC25L4CNE4
ADS8381IPFBT	CD74HCT4543E	SN74AS805BNE4	TLC25M2ACP
ADS8381IPFBTG4	CD74HCT4543EE4	SN74AS808BN	TLC25M2ACPE4
ADS8401IBPFBT	CD74HCT533E	SN74AS808BNE4	TLC25M2CP
ADS8401IBPFBTG4	CD74HCT533EE4	SN74AS832BN	TLC25M2CPE4
ADS8401IPFBR	CD74HCT534E	SN74AS832BNE4	TLC25M4BCN
ADS8401IPFBRG4	CD74HCT534EE4	SN74AVC4T245RGYR	TLC25M4BCNE4
ADS8401IPFBT	CD74HCT540E	SN74AVC6T245PWR	TLC25M4CN
ADS8401IPFBTG4	CD74HCT540EE4	SN74AVC6T245RGYR	TLC25M4CNE4
ADS8402IBPFBT	CD74HCT541E	SN74AVCH4T245RGYR	TLC2652ACN
ADS8402IBPFBTG4	CD74HCT541EE4	SN74BCT125AN	TLC2652ACNE4
ADS8402IPFBT	CD74HCT563E	SN74BCT125ANE4	TLC2652ACP
ADS8402IPFBTG4	CD74HCT563EE4	SN74BCT126AN	TLC2652ACPE4
ADS8405IBPFBR	CD74HCT564E	SN74BCT126ANE4	TLC2652AIN
ADS8405IBPFBRG4	CD74HCT564EE4	SN74BCT2240N	TLC2652AINE4
ADS8405IBPFBT	CD74HCT573E	SN74BCT2240NE4	TLC2652AIP
ADS8405IBPFBTG4	CD74HCT573EE4	SN74BCT2244N	TLC2652AIPE4
ADS8405IPFBR	CD74HCT574E	SN74BCT2244NE4	TLC2652CN
ADS8405IPFBRG4	CD74HCT574EE4	SN74BCT2245N	TLC2652CNE4
ADS8405IPFBT	CD74HCT597E	SN74BCT2245NE4	TLC2652CP
ADS8405IPFBTG4	CD74HCT597EE4	SN74BCT240N	TLC2652CPE4
ADS8406IBPFBR	CD74HCT640E	SN74BCT240NE4	TLC2652IP
ADS8406IBPFBTG4	CD74HCT640EE4	SN74BCT2414N	TLC2652IPE4
ADS8406IBPFBT	CD74HCT670E	SN74BCT2414NE4	TLC2654ACP
ADS8406IBPFBTG4	CD74HCT670EE4	SN74BCT241N	TLC2654ACPE4
ADS8406IPFBT	CD74HCT688E	SN74BCT241NE4	TLC2654AIP
ADS8406IPFBTG4	CD74HCT688EE4	SN74BCT244N	TLC2654AIPE4
ADS8408IBDRCR	CD74HCT7046AE	SN74BCT244NE4	TLC2654CN
ADS8408IBDRCT	CD74HCT7046AEE4	SN74BCT245N	TLC2654CNE4
ADS8408IDRCR	CD74HCT73E	SN74BCT245NE4	TLC2654CP
ADS8408IDRCT	CD74HCT73EE4	SN74BCT373N	TLC2654CPE4
ADS8411IBPFBR	CD74HCT74E	SN74BCT373NE4	TLC2654IP
ADS8411IBPFBTG4	CD74HCT74EE4	SN74BCT374N	TLC2654IPE4
ADS8411IPFBT	CD74HCT75E	SN74BCT374NE4	TLC271ACP
ADS8411IPFBTG4	CD74HCT75EE4	SN74BCT540AN	TLC271ACPE4
ADS8411IPFBT	CD74HCT85E	SN74BCT540ANE4	TLC271AIP

ADS8411IPFBTG4	CD74HCT85EE4	SN74BCT541AN	TLC271AIPe4
ADS8412IBPFBR	CD74HCT86E	SN74BCT541ANE4	TLC271BCP
ADS8412IBPFBRG4	CD74HCT86EE4	SN74BCT573N	TLC271BCPE4
ADS8412IBPFBT	CD74HCT93E	SN74BCT573NE4	TLC271BIP
ADS8412IBPFBTG4	CD74HCT93EE4	SN74BCT574N	TLC271BIPE4
ADS8412IPFBT	CD74HCU04E	SN74BCT574NE4	TLC271CP
ADS8412IPFBTG4	CD74HCU04EE4	SN74BCT623N	TLC271CPE4
ADS8422IBPFBR	CDC1104RVKR	SN74BCT623NE4	TLC271IP
ADS8422IBPFBRG4	CDCLVC1310RHBR	SN74BCT640N	TLC271IPE4
ADS8422IBPFBT	CDCLVP111VFP	SN74BCT640NE4	TLC272ACP
ADS8422IBPFBTG4	CDCLVP111VFPR	SN74BCT756N	TLC272ACPE4
ADS8422IPFBR	CDCUN1310RGZR	SN74BCT756NE4	TLC272AIP
ADS8422IPFBRG4	CDCUN1310SRGZR	SN74BCT757N	TLC272AIPE4
ADS8422IPFBT	CY74FCT2245ATPC	SN74BCT757NE4	TLC272BCP
ADS8422IPFBTG4	CY74FCT2245ATPCE4	SN74BCT760N	TLC272BCPE4
ADS8517IBPW	CY74FCT244ATPC	SN74BCT760NE4	TLC272BIP
ADS8517IBPWR	CY74FCT244ATPCE4	SN74CB3Q3305PWR-P	TLC272BIPE4
ADS8517IPW	CY74FCT245ATPC	SN74CB3Q3306APWR-P	TLC272CP
ADS8517IPWR	CY74FCT245ATPCE4	SN74CB3Q3306PW	TLC272CPE4
ADS8634SRGER	CY74FCT374ATPC	SN74CBTLV3257RGR	TLC272IP
ADS8634SRGET	CY74FCT374ATPCE4	SN74F169N	TLC272IPE4
ADS8638SRGER	CY74FCT541ATPC	SN74F169NE4	TLC274ACN
ADS8638SRGET	CY74FCT541ATPCE4	SN74F240N	TLC274ACNE4
ADS8660IBRHBR	CY74FCT573ATPC	SN74F240NE4	TLC274AIN
ADS8660IRHBR	CY74FCT573ATPCE4	SN74F241N	TLC274AINE4
ADS8660IRHBT	DAC1282IPW	SN74F241NE4	TLC274BCN
AFE030AIRGZR	DAC1282IPWR	SN74F244N	TLC274BCNE4
AFE030AIRGZT	DAC7632VFBT	SN74F244NE4	TLC274BIN
AFE031AIRGZR	DAC7632VFBTG4	SN74F245N	TLC274BINE4
AFE031AIRGZT	DAC7632VFR	SN74F245NE4	TLC274CN
AM26C31CN	DAC7632VFRG4	SN74F299N	TLC274CNE4
AM26C31CNE4	DAC7632VFT	SN74F299NE4	TLC274IN
AM26C31IN	DAC7632VFTG4	SN74F373N	TLC274INE4
AM26C31INE4	DAC7641Y/250	SN74F373NE4	TLC277CP
AM26C32CN	DAC7641Y/250G4	SN74F374N	TLC277CPE4
AM26C32CNE4	DAC7641YB/250	SN74F374NE4	TLC277IP
AM26C32IN	DAC7641YB/250G4	SN74F377AN	TLC277IPE4
AM26C32INE4	DAC7642VFBT	SN74F377ANE4	TLC279CN
AMC7824SRSLR	DAC7642VFBTG4	SN74F521N	TLC279CNE4
AMC7824SRSLT	DAC7642VFT	SN74F521NE4	TLC279IN
AMC7891SRHHR	DAC7642VFTG4	SN74F541N	TLC279INE4
AMC7891SRHHT	DAC7643VFBR	SN74F541NE4	TLC27L1ACP
AMC80AIPW	DAC7643VFBRG4	SN74F573N	TLC27L1ACPE4
AMC80AIPWR	DAC7750IPWP	SN74F573NE4	TLC27L1CP
BQ2002CPN	DAC7750IPWPR	SN74F574N	TLC27L1CPE4
BQ2002CPNE4	DAC7750IRHAR	SN74F574NE4	TLC27L1IP
BQ2002EPN	DAC7750IRHAT	SN74GTL2003PW	TLC27L1IPE4
BQ2002EPNE4	DAC7760IPWP	SN74GTL2003PWR	TLC27L2ACP
BQ2002FPN	DAC7760IPWPR	SN74HC00AN	TLC27L2ACPE4
BQ2002FPNE4	DAC7760IRHAR	SN74HC00AN-P	TLC27L2AIP
BQ2002GPN	DAC7760IRHAT	SN74HC00AN-P2	TLC27L2AIPE4
BQ2002GPNE4	DAC8164IAPW	SN74HC00ANE4	TLC27L2BCP
BQ2002PN	DAC8164IAPWG4	SN74HC00N	TLC27L2BCPE4
BQ2002PNE4	DAC8164IAPWR	SN74HC00N-P	TLC27L2BIP
BQ2002TPN	DAC8164IAPWRG4	SN74HC00N-P2	TLC27L2BIPE4
BQ2002TPNE4	DAC8164IBPW	SN74HC00NE4	TLC27L2CP
BQ2003PN	DAC8164IBPWG4	SN74HC02AN	TLC27L2CPE4
BQ2003PN-N	DAC8164IBPWR	SN74HC02AN-P	TLC27L2IP
BQ2003PNE4	DAC8164IBPWRG4	SN74HC02AN-P2	TLC27L2IPE4
BQ2057TTS	DAC8164ICPW	SN74HC02ANE4	TLC27L4ACN

BQ2057TTSG4	DAC8164ICPWG4	SN74HC02N	TLC27L4ACNE4
BQ2057TTSTR	DAC8164ICPWR	SN74HC02N-P	TLC27L4AIN
BQ2057TTSTRG4	DAC8164ICPWRG4	SN74HC02N-P2	TLC27L4AINE4
BQ2057WTS	DAC8164IDPW	SN74HC02NE4	TLC27L4BCN
BQ2057WTSG4	DAC8164IDPWG4	SN74HC03N	TLC27L4BCNE4
BQ20695ADBT-V100	DAC8164IDPWR	SN74HC03NE4	TLC27L4BIN
BQ20695ADBT-V400	DAC8164IDPWRG4	SN74HC04AN	TLC27L4BINE4
BQ20695ADBT-V500	DAC8165IAPW	SN74HC04ANE4	TLC27L4CN
BQ20695ADBTR-V100	DAC8165IAPWG4	SN74HC04N	TLC27L4CNE4
BQ20695ADBTR-V400	DAC8165IAPWR	SN74HC04N-P	TLC27L4IN
BQ20695ADBTR-V500	DAC8165IAPWRG4	SN74HC04NE4	TLC27L4INE4
BQ2083DBT-V133	DAC8165IBPW	SN74HC05AN	TLC27L7CP
BQ2083DBTR-V133	DAC8165IBPWG4	SN74HC05ANE4	TLC27L7CPE4
BQ20857DBT-V250	DAC8165IBPWR	SN74HC05N	TLC27L7IP
BQ20857DBTR-V250	DAC8165IBPWRG4	SN74HC05NE4	TLC27L7IPE4
BQ20Z402PW	DAC8165ICPW	SN74HC08AN	TLC27L9CN
BQ20Z402PWR	DAC8165ICPWG4	SN74HC08ANE4	TLC27L9CNE4
BQ20Z602DBT	DAC8165ICPWR	SN74HC08N	TLC27L9IN
BQ20Z602DBTR	DAC8165ICPWRG4	SN74HC08N-P	TLC27L9INE4
BQ24600RVAR	DAC8165IDPW	SN74HC08N-P2	TLC27M2ACP
BQ24600RVAT	DAC8165IDPWG4	SN74HC08NE4	TLC27M2ACPE4
BQ24610RGER	DAC8165IDPWR	SN74HC109AN	TLC27M2AIP
BQ24610RGET	DAC8165IDPWRG4	SN74HC109ANE4	TLC27M2AIPE4
BQ24616RGER	DAC8564IAPW	SN74HC109N	TLC27M2BCP
BQ24616RGET	DAC8564IAPWG4	SN74HC109NE4	TLC27M2BCPE4
BQ24617RGER	DAC8564IAPWR	SN74HC10AN	TLC27M2BIP
BQ24617RGET	DAC8564IAPWRG4	SN74HC10AN-P	TLC27M2BIPE4
BQ24618RGER	DAC8564IBPW	SN74HC10ANE4	TLC27M2CP
BQ24618RGET	DAC8564IBPWG4	SN74HC10N	TLC27M2CPE4
BQ24620RVAR	DAC8564IBPWR	SN74HC10N-P	TLC27M2IP
BQ24620RVAT	DAC8564IBPWRG4	SN74HC10NE4	TLC27M2IPE4
BQ24630RGER	DAC8564ICPW	SN74HC112N	TLC27M4ACN
BQ24630RGET	DAC8564ICPWG4	SN74HC112NE4	TLC27M4ACNE4
BQ24640RVAR	DAC8564ICPWR	SN74HC11AN	TLC27M4AIN
BQ24640RVAT	DAC8564ICPWRG4	SN74HC11ANE4	TLC27M4AINE4
BQ24737RGRT	DAC8564IDPW	SN74HC11N	TLC27M4BCN
BQ24742RHDR	DAC8564IDPWG4	SN74HC11NE4	TLC27M4BCNE4
BQ24742RHDT	DAC8564IDPWR	SN74HC125AN	TLC27M4BIN
BQ25504RGTR	DAC8564IDPWRG4	SN74HC125ANE4	TLC27M4BINE4
BQ25504RGTT	DAC8565IAPW	SN74HC125N	TLC27M4CN
BQ2942A0PW	DAC8565IAPWG4	SN74HC125NE4	TLC27M4CNE4
BQ2942A0PWR	DAC8565IAPWR	SN74HC126AN	TLC27M4IN
BQ2942A9PW	DAC8565IAPWRG4	SN74HC126ANE4	TLC27M4INE4
BQ2942A9PWR	DAC8565IBPW	SN74HC126N	TLC27M7CP
BQ2942B0PW	DAC8565IBPWG4	SN74HC126NE4	TLC27M7CPE4
BQ2942B0PWR	DAC8565IBPWR	SN74HC132AN	TLC27M7IP
BQ2942B9PW	DAC8565IBPWRG4	SN74HC132AN-P	TLC27M7IPE4
BQ2942B9PWR	DAC8565ICPW	SN74HC132ANE4	TLC27M9CN
BQ29441DRBT	DAC8565ICPWG4	SN74HC132N	TLC27M9CNE4
BQ29442DRBR	DAC8565ICPWR	SN74HC132N-P	TLC27M9IN
BQ29442DRBT	DAC8565ICPWRG4	SN74HC132N-P2	TLC27M9INE4
BQ29443DRBR	DAC8565IDPW	SN74HC132NE4	TLC339CN
BQ29443DRBT	DAC8565IDPWG4	SN74HC138AN	TLC339CNE4
BQ29444DRBR	DAC8565IDPWR	SN74HC138ANE4	TLC339IN
BQ29444DRBT	DAC8565IDPWRG4	SN74HC138N	TLC339INE4
BQ2944L0ADRBR	DAC8750IPWP	SN74HC138N-P	TLC352CP
BQ2944L0ADRBT	DAC8750IPWPR	SN74HC138N-P2	TLC352CPE4
BQ2944L1DRBR	DAC8750IRHAR	SN74HC138NE4	TLC352IP
BQ2944L1DRBT	DAC8750IRHAT	SN74HC139AN	TLC352IPE4
BQ2944L2DRBR	DAC8760IPWP	SN74HC139ANE4	TLC354CN

BQ2944L2DRBT	DAC8760IPWPR	SN74HC139N	TLC354CNE4
BQ2944L3DRBR	DAC8760IRHAR	SN74HC139N-P	TLC3702CP
BQ2944L3DRBT	DAC8760IRHAT	SN74HC139N-P2	TLC3702CPE4
BQ2944L4DRBR	DIR9001PWR	SN74HC139NE4	TLC3702IP
BQ2944L4DRBT	DIR9001PWRG4	SN74HC148AN	TLC3702IPE4
BQ34Z801DBT	DIR9001S1PWR	SN74HC148ANE4	TLC3704CN
BQ34Z801DBTR	DIR9001S1PWRG4	SN74HC148N	TLC3704CNE4
BQ76923PW	DIX9211PT	SN74HC148NE4	TLC3704IN
BQ76923PWR	DIX9211PTR	SN74HC14AN	TLC3704INE4
BQ76925PW	FX001	SN74HC14AN-P	TLC372CP
BQ76925PWR	GD75232N	SN74HC14AN-P2	TLC372CPE4
BQ76PL536APAP	GD75232NE4	SN74HC14ANE4	TLC372IP
BQ76PL536APAPR	ICL7652P	SN74HC14N	TLC372IPE4
BQ76PL536APAPT	ICL7652PE4	SN74HC14N-P	TLC374CN
BQ8050DBT-D1	INA110KP	SN74HC14N-P2	TLC374CN-A
BQ8055DBT-D1	INA110KPG4	SN74HC14NE4	TLC374CN-AE4
BQ8055DBTR-D1	INA116PA	SN74HC151AN	TLC374CNE4
BUF08832AIPWPR	INA116PAG4	SN74HC151ANE4	TLC374IN
BUF18830AIRGFR	INA826AIDRGR	SN74HC151N	TLC374INE4
BUF18830AIRGFT	INA826AIDRGT	SN74HC151NE4	TLC393CP
CD4504BE-E	INA829AIDRGR	SN74HC153AN	TLC393CPE4
CD74AC00E	INA829AIDRGT	SN74HC153ANE4	TLC393IP
CD74AC00EE4	INA829IDRGR	SN74HC153N	TLC393IPE4
CD74AC02E	INA829IDRGT	SN74HC153NE4	TLC540IN
CD74AC02EE4	LM358PWRG4-JF	SN74HC157AN	TLC540INE4
CD74AC04E	MAX202CN	SN74HC157ANE4	TLC541IN
CD74AC04EE4	MAX202IN	SN74HC157N	TLC541INE4
CD74AC05E	MAX232ECN	SN74HC157NE4	TLC542CN
CD74AC05EE4	MAX232ECNE4	SN74HC158N	TLC542CNE4
CD74AC08E	MAX232EIN	SN74HC158NE4	TLC542IN
CD74AC08EE4	MAX232EINE4	SN74HC161AN	TLC542INE4
CD74AC109E	MPC508AP	SN74HC161ANE4	TLC548CP
CD74AC109EE4	MPC508APG4	SN74HC161N	TLC548CPE4
CD74AC10E	MPC509AP	SN74HC161N-P	TLC548IP
CD74AC10EE4	MPC509APG4	SN74HC161N-P2	TLC548IPE4
CD74AC112E	ONET1121LRGER	SN74HC161NE4	TLC549CP
CD74AC112EE4	ONET1121LRGET	SN74HC163AN	TLC549CPE4
CD74AC138E	ONET1141LRGER	SN74HC163ANE4	TLC549IP
CD74AC138EE4	ONET1141LRGET	SN74HC163N	TLC549IPE4
CD74AC139E	ONET1151MRGTR	SN74HC163N-P	TLC551CP
CD74AC139EE4	ONET1151MRGTT	SN74HC163NE4	TLC551CPE4
CD74AC14E	ONET8541TRGT	SN74HC164AN	TLC552CN
CD74AC14EE4	OPA1604AIPW	SN74HC164ANE4	TLC552CNE4
CD74AC151E	OPA1604AIPWR	SN74HC164N	TLC555CP
CD74AC151EE4	OPA211AIDRGR	SN74HC164N-P	TLC555CPE4
CD74AC153E	OPA211AIDRGRG4	SN74HC164N-P2	TLC555IP
CD74AC153EE4	OPA211AIDRGT	SN74HC164NE4	TLC555IP-P
CD74AC157E	OPA211AIDRGTG4	SN74HC165AN	TLC555IPE4
CD74AC157EE4	OPA211IDRGR	SN74HC165ANE4	TLC556CN
CD74AC161E	OPA211IDRGT	SN74HC165N	TLC556CNE4
CD74AC161EE4	OPA2314AIDRBR	SN74HC165N-P	TLC556IN
CD74AC163E	OPA2314AIDRBT	SN74HC165N-P2	TLC556INE4
CD74AC163EE4	OPA2320AIDRGR	SN74HC165NE4	TLC5615CP
CD74AC164E	OPA2320AIDRGT	SN74HC166AN	TLC5615CPE4
CD74AC164EE4	OPA2322AIDRGR	SN74HC166ANE4	TLC5615IP
CD74AC174E	OPA2322AIDRGT	SN74HC166N	TLC5615IPE4
CD74AC174EE4	OPA2355AIRGTR	SN74HC166NE4	TLC5916IN
CD74AC20E	OPA4170AIPW	SN74HC174AN	TLC5916INE4
CD74AC20EE4	OPA4170AIPWR	SN74HC174ANE4	TLC5917IN
CD74AC240E	OPA4171AIPW	SN74HC174N	TLC5917INE4

CD74AC240EE4	OPA4171AIPWR	SN74HC174N-P	TLC59210IN
CD74AC244E	OPA4241PA	SN74HC174N-P2	TLC59211IN
CD74AC244EE4	OPA4241PAG4	SN74HC174NE4	TLC59212IN
CD74AC245E	OPA4314AIPW	SN74HC175AN	TLC59224FIDBTR
CD74AC245EE4	OPA4314AIPWR	SN74HC175AN-P	TLC5928PW
CD74AC257E	OPA4322AIPW	SN74HC175ANE4	TLC5928PWG4
CD74AC257EE4	OPA4322AIPWR	SN74HC175N	TLC5928PWR
CD74AC273E	OPA4322SAIPW	SN74HC175N-P	TLC5928PWRG4
CD74AC273EE4	OPA4322SAIPWR	SN74HC175NE4	TLC59461PWP
CD74AC280E	OPA564AIPWP	SN74HC191N	TLC5946PW
CD74AC280EE4	OPA564AIPWPR	SN74HC191NE4	TLC5946PWG4
CD74AC283E	PCA9538RGTR	SN74HC193AN	TLC5946PWR
CD74AC283EE4	PCA9544ARGWR	SN74HC193ANE4	TLC5946PWRG4
CD74AC32E	PCA9545ARGWR	SN74HC193N	TLC5947DAP-P
CD74AC32EE4	PCF8574AN	SN74HC193NE4	TLC5947DAP-PG4
CD74AC373E	PCF8574ANE4	SN74HC20AN	TLC59601DA
CD74AC373EE4	PCF8574N	SN74HC20ANE4	TLC59601DAR
CD74AC374E	PCF8574NE4	SN74HC20N	TLC5960DA
CD74AC374EE4	PCF8575CRHLR	SN74HC20NE4	TLC5960DAR
CD74AC541E	PCI950PT	SN74HC21AN	TLC7524CN
CD74AC541EE4	PCI950PTG4	SN74HC21ANE4	TLC7524CNE4
CD74AC573E	PCM1602AMPTR	SN74HC21N	TLC7524EN
CD74AC573EE4	PCM1770PW	SN74HC21N-P	TLC7524ENE4
CD74AC574E	PCM1770PWG4	SN74HC21N-P2	TLC7524IN
CD74AC574EE4	PCM1772PW	SN74HC21NE4	TLC7524INE4
CD74AC623E	PCM1772PWG4	SN74HC240AN	TLC81161PWR
CD74AC623EE4	PCM2706CPJT	SN74HC240ANE4	TLC8216FIPW-P
CD74AC74E	PCM2706CPJTR	SN74HC240N	TLC8216FIPWR-P
CD74AC74EE4	PCM2707CPJT	SN74HC240N-P	TLC8224FIDBT-P
CD74AC86E	PCM2707CPJTR	SN74HC240N-P2	TLC8416FIPW-P
CD74AC86EE4	PCM2912AE3PJT	SN74HC240NE4	TLC8424FIDBT-P
CD74ACT00E	PCM2912AE3PJTR	SN74HC241N	TLE2301INE
CD74ACT00EE4	PCM2912AE4PJT	SN74HC241NE4	TLE2301INEE4
CD74ACT02E	PCM2912AE4PJTR	SN74HC244AN	TLS1233N
CD74ACT02EE4	PCM9211PT	SN74HC244ANE4	TLV1233NE4
CD74ACT04E	PCM9211PTR	SN74HC244N	TLV0831CP
CD74ACT04EE4	PTPS65854ZQZR	SN74HC244N-P	TLV0831CPE4
CD74ACT05E	PTPS658600AZQZ	SN74HC244N-P1	TLV0831IP
CD74ACT05EE4	PTPS658600AZQZR	SN74HC244N-P2	TLV0831IPE4
CD74ACT08E	PTPS658600AZQZT	SN74HC244NE4	TLV0832CP
CD74ACT08EE4	SN0702077PWR	SN74HC245AN	TLV0832CPE4
CD74ACT109E	SN0702077PWRG4	SN74HC245ANE4	TLV0832IP
CD74ACT109EE4	SN0911044PWR	SN74HC245N	TLV0832IPE4
CD74ACT10E	SN105225DBTRG4	SN74HC245N-P	TLV0834IN
CD74ACT10EE4	SN1107049CPAGR	SN74HC245N-P1	TLV0834INE4
CD74ACT138E	SN1107083DAR	SN74HC245NE4	TLV0838CN
CD74ACT138EE4	SN20060585PHPR	SN74HC251AN	TLV0838CNE4
CD74ACT139E	SN20060585PHPRG4	SN74HC251ANE4	TLV1543CN
CD74ACT139EE4	SN20060590PHPR	SN74HC251N	TLV1543CNE4
CD74ACT14E	SN20060590PHPRG4	SN74HC251NE4	TLV1549CP
CD74ACT14EE4	SN64BCT125AN	SN74HC253N	TLV1549CPE4
CD74ACT153E	SN64BCT125ANE4	SN74HC253NE4	TLV1549IP
CD74ACT153EE4	SN64BCT126AN	SN74HC257AN	TLV1549IPE4
CD74ACT157E	SN64BCT126ANE4	SN74HC257ANE4	TLV2322IP
CD74ACT157EE4	SN65C1154N	SN74HC257N	TLV2322IPE4
CD74ACT161E	SN65C1154NE4	SN74HC257NE4	TLV2324IN
CD74ACT161EE4	SN65C1168N	SN74HC258AN	TLV2324INE4
CD74ACT163E	SN65C1168NE4	SN74HC258ANE4	TLV2332IP
CD74ACT163EE4	SN65C23243DGG	SN74HC258N	TLV2332IPE4
CD74ACT164E	SN65C23243DGG4	SN74HC258NE4	TLV2334IN

CD74ACT164EE4	SN65C23243DGGG4	SN74HC259AN	TLV2334INE4
CD74ACT174E	SN65C23243DGGR	SN74HC259ANE4	TLV2341IP
CD74ACT174EE4	SN65C23243DGGRE4	SN74HC259N	TLV2341IPE4
CD74ACT175E	SN65C23243DGGRG4	SN74HC259NE4	TLV2342IP
CD74ACT175EE4	SN65HVD05P	SN74HC266AN	TLV2342IPE4
CD74ACT20E	SN65HVD05PE4	SN74HC266ANE4	TLV2344IN
CD74ACT20EE4	SN65HVD06P	SN74HC266N	TLV2344INE4
CD74ACT238E	SN65HVD06PE4	SN74HC266NE4	TLV2352IP
CD74ACT238EE4	SN65HVD07P	SN74HC273AN	TLV2352IPE4
CD74ACT240E	SN65HVD07PE4	SN74HC273AN-P	TLV2354IN
CD74ACT240EE4	SN65HVD08P	SN74HC273ANE4	TLV2354INE4
CD74ACT241E	SN65HVD08PE4	SN74HC273N	TLV2543CN
CD74ACT241EE4	SN65HVD09DGG	SN74HC273N-P	TLV2543CNE4
CD74ACT244E	SN65HVD09DGGR	SN74HC273N-P1	TLV2543IN
CD74ACT244EE4	SN65HVD10P	SN74HC273N-P2	TLV2543INE4
CD74ACT245E	SN65HVD10PE4	SN74HC273NE4	TLV2760IP
CD74ACT245EE4	SN65HVD11P	SN74HC27AN	TLV2760IPE4
CD74ACT253E	SN65HVD11PE4	SN74HC27ANE4	TLV2761IP
CD74ACT253EE4	SN65HVD12P	SN74HC27N	TLV2761IPE4
CD74ACT257E	SN65HVD12PE4	SN74HC27N-P	TLV2764IN
CD74ACT257EE4	SN65HVD22P	SN74HC27N-P2	TLV2764INE4
CD74ACT273E	SN65HVD22PE4	SN74HC27NE4	TLV2770AIP
CD74ACT273EE4	SN65HVD23P	SN74HC32AN	TLV2770AIPPE4
CD74ACT280E	SN65HVD23PE4	SN74HC32AN-P	TLV2770CP
CD74ACT280EE4	SN65HVD251P	SN74HC32ANE4	TLV2770CPE4
CD74ACT283E	SN65HVD251PE4	SN74HC32N	TLV2770IP
CD74ACT283EE4	SN65HVD62RGT	SN74HC32N-P	TLV2770IPE4
CD74ACT32E	SN65LBC174AN	SN74HC32N-P2	TLV2772AIP
CD74ACT32EE4	SN65LVDS349PW	SN74HC32NE4	TLV2772AIPPE4
CD74ACT373E	SN65LVDS349PWR	SN74HC365AN	TLV2772CP
CD74ACT373EE4	SN700835N	SN74HC365ANE4	TLV2772CPE4
CD74ACT374E	SN74107N	SN74HC365N	TLV2772IP
CD74ACT374EE4	SN74107NE4	SN74HC365NE4	TLV2772IPE4
CD74ACT540E	SN7410N	SN74HC367AN	TLV2773AIN
CD74ACT540EE4	SN7410NE4	SN74HC367ANE4	TLV2773AINE4
CD74ACT541E	SN74123N	SN74HC367N	TLV2773IN
CD74ACT541EE4	SN74123NE4	SN74HC367NE4	TLV2773INE4
CD74ACT573E	SN74ABT125N	SN74HC368AN	TLV2774AIN
CD74ACT573EE4	SN74ABT125NE4	SN74HC368ANE4	TLV2774AINE4
CD74ACT574E	SN74ABT126N	SN74HC368N	TLV2774CN
CD74ACT574EE4	SN74ABT126NE4	SN74HC368NE4	TLV2774CNE4
CD74ACT74E	SN74ABT2240AN	SN74HC373AN	TLV2774IN
CD74ACT74EE4	SN74ABT2240ANE4	SN74HC373ANE4	TLV2774INE4
CD74ACT86E	SN74ABT2241N	SN74HC373N	TLV2775AIN
CD74ACT86EE4	SN74ABT2241NE4	SN74HC373NE4	TLV2775AINE4
CD74FCT244ATE	SN74ABT2244AN	SN74HC374AN	TLV2775CN
CD74FCT244ATEE4	SN74ABT2244ANE4	SN74HC374ANE4	TLV2775CNE4
CD74FCT244E	SN74ABT2245N	SN74HC374N	TLV2782IP
CD74FCT244EE4	SN74ABT2245NE4	SN74HC374NE4	TLV2782IPE4
CD74FCT245E	SN74ABT240AN	SN74HC377AN	TLV2783IN
CD74FCT245EE4	SN74ABT240ANE4	SN74HC377ANE4	TLV2783INE4
CD74FCT273E	SN74ABT241AN	SN74HC377N	TLV2785IN
CD74FCT273EE4	SN74ABT241ANE4	SN74HC377NE4	TLV2785INE4
CD74FCT374E	SN74ABT244AN	SN74HC393AN	TLV344IPW
CD74FCT374EE4	SN74ABT244ANE4	SN74HC393ANE4	TLV344IPWR
CD74FCT541E	SN74ABT245BN	SN74HC393N	TLV5616CP
CD74FCT541EE4	SN74ABT245BNE4	SN74HC393N-P	TLV5616CPE4
CD74HC00E	SN74ABT273N	SN74HC393N-P2	TLV5616IP
CD74HC00EE4	SN74ABT273NE4	SN74HC393NE4	TLV5616IPE4
CD74HC02E	SN74ABT373N	SN74HC4020AN	TLV5618ACP

CD74HC02EE4	SN74ABT373NE4	SN74HC4020AN-P	TLV5618ACPE4
CD74HC03E	SN74ABT374AN	SN74HC4020AN-P2	TLV5618AIP
CD74HC03EE4	SN74ABT374ANE4	SN74HC4020ANE4	TLV5618AIPe4
CD74HC04E	SN74ABT377AN	SN74HC4020N	TMDS361GBPAGR
CD74HC04EE4	SN74ABT377ANE4	SN74HC4020N-P	TMDS371PAG
CD74HC08E	SN74ABT533AN	SN74HC4020N-P2	TMDS371PAGR
CD74HC08EE4	SN74ABT533ANE4	SN74HC4020NE4	TMP512AIRSAR
CD74HC107E	SN74ABT534AN	SN74HC4040AN	TMP512AIRSAT
CD74HC107E-P	SN74ABT534ANE4	SN74HC4040ANE4	TPA3004D2PHP
CD74HC107EE4	SN74ABT540N	SN74HC4040N	TPA3004D2PHPG4
CD74HC109E	SN74ABT540NE4	SN74HC4040N-P	TPA3100D2PHPR-P
CD74HC109EE4	SN74ABT541BN	SN74HC4040N-P2	TPA3100D2PHPR-PG4
CD74HC10E	SN74ABT541BNE4	SN74HC4040NE4	TPA3122D2N
CD74HC10EE4	SN74ABT573AN	SN74HC4060N	TPA3125D2N
CD74HC112E	SN74ABT573ANE4	SN74HC4060N-P2	TPA6021A4N
CD74HC112EE4	SN74ABT574AN	SN74HC4060NE4	TPA6021A4NE4
CD74HC11E	SN74ABT574ANE4	SN74HC4066N	TPA6132A2ZSZR
CD74HC11EE4	SN74ABT620N	SN74HC4066NE4	TPD12S016PWR
CD74HC123E	SN74ABT620NE4	SN74HC42N	TPIC6B273N-P
CD74HC123E-P	SN74ABT623N	SN74HC42NE4	TPIC6B596N-P
CD74HC123EE4	SN74ABT623NE4	SN74HC4851N	TPIC6B596N-P2
CD74HC125E	SN74ABT640N	SN74HC4851NE4	TPIC9201N
CD74HC125EE4	SN74ABT640NE4	SN74HC4852N	TPIC9201NE4
CD74HC126E	SN74ABTH245N	SN74HC4852NE4	TPL0102-100PWR
CD74HC126EE4	SN74ABTH245NE4	SN74HC540AN	TPL8002-25PWR
CD74HC132E	SN74AC00N	SN74HC540ANE4	TPL9201N
CD74HC132EE4	SN74AC00NE4	SN74HC540N	TPL9201NE4
CD74HC137E	SN74AC04N	SN74HC540NE4	TPS2113ADRBR
CD74HC137EE4	SN74AC04NE4	SN74HC541AN	TPS2113ADRBT
CD74HC138E	SN74AC08N	SN74HC541ANE4	TPS2350PW
CD74HC138EE4	SN74AC08NE4	SN74HC541N	TPS2350PWG4
CD74HC139E	SN74AC10N	SN74HC541N-P	TPS2350PWR
CD74HC139EE4	SN74AC10NE4	SN74HC541N-P1	TPS2350PWRG4
CD74HC147E	SN74AC11N	SN74HC541N-P2	TPS2386PW
CD74HC147EE4	SN74AC11NE4	SN74HC541NE4	TPS2386PWR
CD74HC14E	SN74AC14N	SN74HC563N	TPS2387PW
CD74HC14EE4	SN74AC14N-P	SN74HC563NE4	TPS2387PWR
CD74HC151E	SN74AC14NE4	SN74HC573AN	TPS2392PW
CD74HC151EE4	SN74AC240N	SN74HC573ANE4	TPS2392PWG4
CD74HC153E	SN74AC240NE4	SN74HC573BN	TPS2392PWR
CD74HC153EE4	SN74AC241N	SN74HC573BNE4	TPS2392PWRG4
CD74HC157E	SN74AC241NE4	SN74HC573N	TPS2393APW
CD74HC157EE4	SN74AC244N	SN74HC573NE4	TPS2393APWG4
CD74HC161E	SN74AC244NE4	SN74HC574AN	TPS2393APWR
CD74HC161EE4	SN74AC245N	SN74HC574ANE4	TPS2393APWRG4
CD74HC163E	SN74AC245NE4	SN74HC574N	TPS2393PW
CD74HC163EE4	SN74AC32N	SN74HC574N-P	TPS2393PWG4
CD74HC164E	SN74AC32NE4	SN74HC574NE4	TPS2393PWR
CD74HC164EE4	SN74AC373N	SN74HC590AN	TPS2393PWRG4
CD74HC165E	SN74AC373NE4	SN74HC590AN-P	TPS2394PW
CD74HC165EE4	SN74AC374N	SN74HC590ANE4	TPS2394PWR
CD74HC166E	SN74AC374NE4	SN74HC594N	TPS24720RGTR
CD74HC166EE4	SN74AC533N	SN74HC594NE4	TPS24720RGTT
CD74HC173E	SN74AC533NE4	SN74HC595AN	TPS40090PW
CD74HC173EE4	SN74AC534N	SN74HC595ANE4	TPS40090PWG4
CD74HC174E	SN74AC534NE4	SN74HC595N	TPS40090PWR
CD74HC174EE4	SN74AC563N	SN74HC595N-P	TPS40090PWRG4
CD74HC175E	SN74AC563NE4	SN74HC595N-P2	TPS40091PW
CD74HC175EE4	SN74AC564N	SN74HC595NE4	TPS40091PWG4
CD74HC190E	SN74AC564NE4	SN74HC623N	TPS40091PWR

CD74HC190EE4	SN74AC573N	SN74HC623NE4	TPS40091PWRG4
CD74HC191E	SN74AC573NE4	SN74HC640AN	TPS40171RGYR-P
CD74HC191EE4	SN74AC574N	SN74HC640ANE4	TPS40171RGYT-P
CD74HC192E	SN74AC574NE4	SN74HC640N	TPS51125ARGER
CD74HC192EE4	SN74AC74N	SN74HC640NE4	TPS51125ARGET
CD74HC193E	SN74AC74NE4	SN74HC645N	TPS53114PWR
CD74HC193EE4	SN74AC86N	SN74HC645NE4	TPS53125PWR
CD74HC194E	SN74AC86NE4	SN74HC682N	TPS53128PW
CD74HC194EE4	SN74ACT00N	SN74HC682NE4	TPS53128PWR
CD74HC195E	SN74ACT00NE4	SN74HC684N	TPS53128RGER
CD74HC195EE4	SN74ACT04N	SN74HC684NE4	TPS53128RGET
CD74HC20E	SN74ACT04NE4	SN74HC688N	TPS53129PW
CD74HC20EE4	SN74ACT08N	SN74HC688NE4	TPS53129PWR
CD74HC21E	SN74ACT08NE4	SN74HC7001N	TPS53129RGER
CD74HC21EE4	SN74ACT10N	SN74HC7001NE4	TPS53129RGET
CD74HC221E	SN74ACT10NE4	SN74HC7002N	TPS53219ARGTR
CD74HC221EE4	SN74ACT11N	SN74HC7002NE4	TPS53219ARGTT
CD74HC237E	SN74ACT11NE4	SN74HC7032N	TPS53219RGTT
CD74HC237EE4	SN74ACT14N	SN74HC7032NE4	TPS53624RHAR
CD74HC238E	SN74ACT14NE4	SN74HC74AN	TPS53624RHAT
CD74HC238E-P	SN74ACT240N	SN74HC74AN-P	TPS59316RTVR
CD74HC238E-P2	SN74ACT240NE4	SN74HC74AN-P2	TPS59620RHAR
CD74HC238EE4	SN74ACT241N	SN74HC74ANE4	TPS59620RHAT
CD74HC240E	SN74ACT241NE4	SN74HC74N	TPS61199PWP
CD74HC240EE4	SN74ACT244N	SN74HC74N-P	TPS61199PWPR
CD74HC241E	SN74ACT244NE4	SN74HC74N-P2	TPS63030DSKR
CD74HC241EE4	SN74ACT245N	SN74HC74NE4	TPS63030DSKRG4
CD74HC243E	SN74ACT245NE4	SN74HC86AN	TPS63030DSKT
CD74HC243EE4	SN74ACT32N	SN74HC86AN-P	TPS63030DSKTG4
CD74HC244E	SN74ACT32NE4	SN74HC86ANE4	TPS63031DSKR
CD74HC244EE4	SN74ACT373N	SN74HC86N	TPS63031DSKRG4
CD74HC245E	SN74ACT373NE4	SN74HC86N-P	TPS63031DSKT
CD74HC245EE4	SN74ACT374N	SN74HC86N-P2	TPS63031DSKTG4
CD74HC251E	SN74ACT374NE4	SN74HC86NE4	TPS65859ZQZR
CD74HC251EE4	SN74ACT533N	SN74HCT00AN	TPS658610ZQZ
CD74HC253E	SN74ACT533NE4	SN74HCT00ANE4	TPS658621EZQZR
CD74HC253EE4	SN74ACT534N	SN74HCT00N	TPS658621EZQZT
CD74HC257E	SN74ACT534NE4	SN74HCT00NE4	TPS658621FZQZR
CD74HC257EE4	SN74ACT563N	SN74HCT02N	TPS658621FZQZT
CD74HC259E	SN74ACT563NE4	SN74HCT02NE4	TPS658622CZQZR
CD74HC259EE4	SN74ACT564N	SN74HCT04AN	TPS658622CZQZT
CD74HC273E	SN74ACT564NE4	SN74HCT04ANE4	TPS658622DZQZR
CD74HC273EE4	SN74ACT573N	SN74HCT04N	TPS658622DZQZT
CD74HC27E	SN74ACT573NE4	SN74HCT04NE4	TPS658623AZQZR
CD74HC27EE4	SN74ACT574N	SN74HCT08AN	TPS658623AZQZT
CD74HC280E	SN74ACT574NE4	SN74HCT08ANE4	TPS658624AZQZR
CD74HC280EE4	SN74ACT74N	SN74HCT08N	TPS7A8001DRBT
CD74HC283E	SN74ACT74NE4	SN74HCT08NE4	TPS7A8101DRBR
CD74HC283EE4	SN74ACT86N	SN74HCT125N	TPS7A8101DRBT
CD74HC297E	SN74ACT86NE4	SN74HCT125NE4	TPS92070PW
CD74HC297EE4	SN74AHC00N	SN74HCT138AN	TPS92070PWR
CD74HC299E	SN74AHC00NE4	SN74HCT138ANE4	TRS202ECN
CD74HC299EE4	SN74AHC02N	SN74HCT138N	TRS202ECNE4
CD74HC30E	SN74AHC02N-P	SN74HCT138NE4	TRS202EIN
CD74HC30EE4	SN74AHC02N-P2	SN74HCT139N	TRS202EINE4
CD74HC32E	SN74AHC02NE4	SN74HCT139NE4	TRS232ECN
CD74HC32EE4	SN74AHC04N	SN74HCT14N	TRS232ECNE4
CD74HC354E	SN74AHC04NE4	SN74HCT14NE4	TRSF23243CDGGR
CD74HC354EE4	SN74AHC05N	SN74HCT157N	TRSF23243CDGGRG4
CD74HC365E	SN74AHC05NE4	SN74HCT157NE4	TRSF3223EIRGWR

CD74HC365EE4	SN74AHC08N	SN74HCT240AN	TS36A41641PWR
CD74HC366E	SN74AHC08N-P	SN74HCT240ANE4	TS36A41642PWR
CD74HC366EE4	SN74AHC08N-P2	SN74HCT240N	TS36A41642RGYR
CD74HC367E	SN74AHC08NE4	SN74HCT240NE4	TS3A5018RGYR
CD74HC367EE4	SN74AHC123AN	SN74HCT244AN	TS3A5018RGYRG4
CD74HC368E	SN74AHC123ANE4	SN74HCT244ANE4	TS3DV20812RHHR
CD74HC368EE4	SN74AHC125N	SN74HCT244N	TS3V712ELRTGR
CD74HC373E	SN74AHC125N-P	SN74HCT244NE4	TS3V713ELRTGR
CD74HC373EE4	SN74AHC125NE4	SN74HCT245AN	TS40A41641PWR
CD74HC374E	SN74AHC126N	SN74HCT245ANE4	TS40A41641RGYR
CD74HC374EE4	SN74AHC126NE4	SN74HCT245N	TS40A41642PWR
CD74HC377E	SN74AHC132N	SN74HCT245NE4	TS40A41642RGYR
CD74HC377EE4	SN74AHC132N-P	SN74HCT257N	TS5V330CPWR
CD74HC390E	SN74AHC132NE4	SN74HCT257NE4	TS5V330CRGYR
CD74HC390EE4	SN74AHC138N	SN74HCT273AN	TS5V522CPWR
CD74HC393E	SN74AHC138N-P	SN74HCT273ANE4	TSC3001IRTW
CD74HC393EE4	SN74AHC138N-P2	SN74HCT273N	TSC3001IRWT
CD74HC4002E	SN74AHC138NE4	SN74HCT273NE4	TUSB1106PWR
CD74HC4002EE4	SN74AHC139N	SN74HCT32AN	TUSB1106PWRG4
CD74HC40103E	SN74AHC139NE4	SN74HCT32ANE4	TUSB2551PW
CD74HC40103EE4	SN74AHC14N	SN74HCT32N	TUSB2551PWG4
CD74HC40105E	SN74AHC14N-P	SN74HCT32NE4	TUSB2551PWR
CD74HC40105EE4	SN74AHC14N-P2	SN74HCT373AN	TUSB2551PWRG4
CD74HC4015E	SN74AHC14NE4	SN74HCT373ANE4	TXB0106PW-P
CD74HC4015EE4	SN74AHC157N	SN74HCT373N	TXS02324RUKR
CD74HC4016E	SN74AHC157NE4	SN74HCT373NE4	TXS02326AMRGER
CD74HC4016EE4	SN74AHC158N	SN74HCT374AN	TXS02326MRGER
CD74HC4017E	SN74AHC158NE4	SN74HCT374ANE4	TXS02326RGER
CD74HC4017EE4	SN74AHC174N	SN74HCT374N	TXS4555RGTR
CD74HC4020E	SN74AHC174N-P	SN74HCT374NE4	TXS4558RUKR
CD74HC4020EE4	SN74AHC174NE4	SN74HCT377N	UCC27323DSDR
CD74HC4024E	SN74AHC240N	SN74HCT377NE4	UCC27323DSDT
CD74HC4024EE4	SN74AHC240NE4	SN74HCT540N	UCC27324DSDR
CD74HC4040E	SN74AHC244N	SN74HCT540NE4	UCC27324DSDT
CD74HC4040EE4	SN74AHC244N-P	SN74HCT541AN	UCC27325DSDR
CD74HC4046AE	SN74AHC244N-P2	SN74HCT541ANE4	UCC27325DSDT
CD74HC4046AEE4	SN74AHC244NE4	SN74HCT541N	UCC27524P
CD74HC4049E	SN74AHC245N	SN74HCT541NE4	UCC2788P
CD74HC4049E-P	SN74AHC245NE4	SN74HCT573AN	UCC2788PE4
CD74HC4049E-P2	SN74AHC273N	SN74HCT573ANE4	UCC28050P
CD74HC4049EE4	SN74AHC273N-P	SN74HCT573N	UCC28050PE4
CD74HC4050E	SN74AHC273NE4	SN74HCT573NE4	UCC28051P
CD74HC4050EE4	SN74AHC32N	SN74HCT574AN	UCC28051PE4
CD74HC4051E	SN74AHC32N-P	SN74HCT574ANE4	UCC28510N
CD74HC4051EE4	SN74AHC32N-P2	SN74HCT574N	UCC28510NE4
CD74HC4052E	SN74AHC32NE4	SN74HCT574NE4	UCC28511N
CD74HC4052EE4	SN74AHC367N	SN74HCT623N	UCC28511NE4
CD74HC4053E	SN74AHC367N-P	SN74HCT623NE4	UCC28512N
CD74HC4053EE4	SN74AHC367NE4	SN74HCT645AN	UCC28512NE4
CD74HC4060E	SN74AHC373N	SN74HCT645ANE4	UCC28513N
CD74HC4060EE4	SN74AHC373N-P	SN74HCT645N	UCC28513NE4
CD74HC4066E	SN74AHC373NE4	SN74HCT645NE4	UCC28514N
CD74HC4066EE4	SN74AHC374N	SN74HCT74AN	UCC28514NE4
CD74HC4075E	SN74AHC374NE4	SN74HCT74ANE4	UCC28515N
CD74HC4075EE4	SN74AHC4066N	SN74HCT74N	UCC28515NE4
CD74HC4094E	SN74AHC4066NE4	SN74HCT74NE4	UCC29002P
CD74HC4094EE4	SN74AHC540N	SN74HCU04AN	UCC29002PE4
CD74HC4094PWR-E	SN74AHC540N-P	SN74HCU04AN-P	UCC2975PW
CD74HC423E	SN74AHC540N-P2	SN74HCU04ANE4	UCC2975PWG4
CD74HC423EE4	SN74AHC540NE4	SN74HCU04N	UCC2976PW

CD74HC42E	SN74AHC541N	SN74HCU04N-P	UCC2976PWG4
CD74HC42EE4	SN74AHC541N-P	SN74HCU04N-P2	UCC2977PW
CD74HC4316E	SN74AHC541N-P2	SN74HCU04NE4	UCC2977PWG4
CD74HC4316EE4	SN74AHC541NE4	SN74LS442N	UCC29910APW
CD74HC4351E	SN74AHC573N	SN74LS442NE4	UCC29910APWR
CD74HC4351EE4	SN74AHC573NE4	SN74LS669N	UCC38050P
CD74HC4352E	SN74AHC574N	SN74LS669NE4	UCC38050PE4
CD74HC4352EE4	SN74AHC574NE4	SN74LV4040AN	UCC38051P
CD74HC4511E	SN74AHC594N	SN74LV4040ANE4	UCC38051PE4
CD74HC4511EE4	SN74AHC594NE4	SN74LV4046AN	UCC39002P
CD74HC4518E	SN74AHC595N	SN74LV4046ANE4	UCC39002PE4
CD74HC4518EE4	SN74AHC595NE4	SN74LV4046ARGYR	UCC3976PW
CD74HC4520E	SN74AHC74N	SN74LV4051AN	UCC3976PWG4
CD74HC4520EE4	SN74AHC74N-P	SN74LV4051ANE4	UCC3977PW
CD74HC4538E	SN74AHC74N-P2	SN74LV4051ARGYR	UCC3977PWG4
CD74HC4538EE4	SN74AHC74NE4	SN74LV4051ARGYRG4	VSP2582RHHR

Product Affected: 1.3 Mil Cu Bond Wire Option			
HPA00674DRBR	TLC5942PWPG4	TPS23757PWR	TPS650007RTET
SN0701064PWPR	TLC5942PWPR	TPS51116PWP-P	TPS65138DRCR
SN0701064PWPRG4	TLC5942PWPRG4	TPS62110GRSAR	TRS3253EIRSMR
TLC5942PWP	TPS23757PW	TPS650007RTER	

Product Affected: 2.0 Mil Cu Bond Wire Option			
TAS5601DCA-P	TPS54620RGYR-P	TPS74001DPTR	
TAS5601DCA-PG4	TPS54620RGYT-P	TPS74001DPTT	

Reference Qualification 1 (TSSOP 0.8 mil Cu wire)

Qualification Data: Approved 11/10/2011

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable specifications.				
Qual Vehicle : SN74LVTH16244ADGGR (MSL=LEVEL1-260CG)				
Package Construction Details				
Assembly Site:	TI Malaysia	Mold Compound:	4209002	
# Pins-Designator, Family:	48-DGG, TSSOP	Mount Compound:	4042500	
Lead Finish, Base	NiPdAu, Cu	Bond Wire:	0.8 Mil Dia. Cu	
Qualification:	<input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results			
Reliability Test	Conditions	Sample Size (PASS/FAIL)		
		Lot#1	Lot#2	Lot#3
*High Temp. Storage Bake	170C (420 Hours)	77/0	77/0	77/0
*Autoclave 121C	121C, 2 atm (96 Hours)	77/0	77/0	77/0
*T/C -65C/150C	-65C/+150°C (500 Cycles)	77/0	77/0	77/0
Manufacturability (Assembly)	(per mfg. Site specification)	Pass	Pass	Pass
Note * Preconditioning sequence: MSL1-260C				

Reference Qualification 2 (TSSOP 0.96 mil Cu wire)

Qualification Data: Approved 3/11/2010

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable specifications.					
Qual Vehicle 1: BQ29330DBT (MSL=LEVEL2-260CG)					
Package Construction Details					
Assembly Site:	TI Malaysia	Mold Compound:	4206193		
# Pins-Designator, Family:	30-DBT, TSSOP	Mount Compound:	4042500		
Lead Finish, Base	NiPdAu, Cu	Bond Wire:	0.96 Mil Dia. Cu		
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results					
Reliability Test	Conditions	Sample Size (PASS/FAIL)			
		Lot#1	Lot#2	Lot#3	
*High Temp. Storage Bake	170C (420 Hours)	77/0	77/0	77/0	
*Autoclave 121C	121C, 2 atm (96 Hours)	77/0	77/0	77/0	
*T/C -65C/150C	-65C/+150°C (500 Cycles)	77/0	77/0	77/0	
Manufacturability (Assembly)	(per mfg. Site specification)	Pass	Pass	Pass	
*Thermal Shock	-65C/+150C (500 Cycles)	77/0	77/0	77/0	
Note * Test requires Moisture Preconditioning					

Qualification Data: Approved 01/03/2011

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.					
Qual Vehicle 1: BUF16821BIPWP (MSL 2-260C)					
Package Construction Details					
Assembly Site:	TI Taiwan	Mold Compound:	4205443		
# Pins-Designator, Family:	28-PWP, TSSOP	Mount Compound:	4208458		
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.96 Mil Dia., Cu		
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results					
Reliability Test	Conditions	Pass / Fail			
		Lot 1	Lot2	Lot 3	
**High Temp. Storage Bake	170C (420 Hrs)	77/0	77/0	77/0	
**Biased HAST	130C/85%RH (96 Hrs)	77/0	77/0	77/0	
**Autoclave 121C	121C, 2 atm (96 Hrs)	77/0	77/0	77/0	
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	77/0	77/0	
**T/C -55C/125C	-55C/+125C (1000 Cyc)	77/0	77/0	77/0	
Manufacturability	(per mfg. Site specification)	Pass	Pass	Pass	
**Thermal Shock	-65C/+150C (500 Cyc)	77/0	77/0	77/0	
Notes: **Tests require preconditioning sequence: MSL2-260C					

Qual Vehicle 2: TAS5086DBT (MSL 2-260C)			
Package Construction Details			
Assembly Site:	TI Taiwan	Mold Compound:	4206193
# Pins-Designator, Family:	38-DBT, TSSOP	Mount Compound:	4042500
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.96 Mil Dia., Cu

Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Pass / Fail		
		Lot 1	Lot2	Lot 3
**High Temp Operating Life (Analog)	155C (240 Hrs), Vddmax	77/0	77/0	77/0
**High Temp. Storage Bake	170C (420 Hrs)	77/0	77/0	77/0
**Biased HAST	130C/85%RH (96 Hrs)	77/0	77/0	77/0
**Autoclave 121C	121C, 2 atm (96 Hrs)	77/0	77/0	77/0
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	77/0	77/0
**T/C -55C/125C	-55C/+125C (1000 Cyc)	77/0	77/0	77/0
Manufacturability	(per mfg. Site specification)	Pass	Pass	Pass
**Thermal Shock	-65C/+150C (500 Cyc)	77/0	77/0	77/0

Notes: **Tests require preconditioning sequence: MSL2-260C

Qualification Data: Approved 07/07/2011

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable specifications.

Qual Vehicle 1: ADS1230IPW (MSL2-260C)				
Package Construction Details				
Assembly Site:	TI Taiwan	Mold Compound:	4206193	
# Pins-Designator, Family:	16-PW, TSSOP	Mount Compound:	4042500	
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.96 Mil Dia., Cu	
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Sample Size (PASS/FAIL)		
		Lot#1	Lot#2	Lot#3
**High Temp. Storage Bake	170C (420 Hours)	77/0	77/0	77/0
**Autoclave 121C	121C, 2 atm (96 Hours)	77/0	77/0	77/0
**T/C -65C/150C	-65C/+150°C (500 Cycles)	77/0	77/0	77/0
Manufacturability (Assembly)	(per mfg. Site specification)	Pass	Pass	Pass

Notes: **Tests require preconditioning sequence: MSL2-260C

Qual Vehicle 2: BUF07704AIPWP (MSL2-260C)			
Package Construction Details			
Assembly Site:	TI Malaysia	Mold Compound:	4205443
# Pins-Designator, Family:	20-PWP, HTSSOP	Mount Compound:	4042504
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.96 Mil Dia., Cu

Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Pass / Fail		
		Lot 1	Lot2	Lot 3
**High Temp. Storage Bake	170C (420 Hrs)	77/0	77/0	77/0
**Autoclave 121C	121C, 2 atm (96 Hrs)	77/0	77/0	77/0
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	77/0	77/0
Manufacturability	(per mfg. Site specification)	Pass	Pass	Pass
Notes: **Preconditioning sequence: MSL2-260C				

Qual Vehicle 3: CDCVF2505PW (MSL1-260C)				
Package Construction Details				
Assembly Site:	TI Malaysia	Mold Compound:	4206193	
# Pins-Designator, Family:	8-PW, TSSOP	Mount Compound:	4042500	
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.96 Mil Dia., Cu	
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Pass / Fail		
		Lot 1	Lot2	Lot 3
**High Temp. Storage Bake	170C (420 Hrs)	77/0	77/0	77/0
**Autoclave 121C	121C, 2 atm (96 Hrs)	77/0	77/0	77/0
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	77/0	77/0
Manufacturability	(per mfg. Site specification)	Pass	Pass	Pass
Notes: **Preconditioning sequence: MSL1-260C				

Qual Vehicle 4: SN75LVDS84ADGG (MSL2-260C)				
Package Construction Details				
Assembly Site:	TI Taiwan	Mold Compound:	4209002	
# Pins-Designator, Family:	48-DGG, TSSOP	Mount Compound:	4042500	
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.96 Mil Dia., Cu	
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Pass / Fail		
		Lot 1	Lot2	Lot 3
**High Temp. Storage Bake	150C (500, 1000 Hrs)	77/0	77/0	77/0
**Unbiased HAST	130C/85%RH (96 Hrs)	77/0	77/0	77/0
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	77/0	77/0
Manufacturability	(per mfg. Site specification)	Pass	Pass	Pass
Notes: **Preconditioning sequence: MSL2-260C				

Qual Vehicle 5: THS7303PW (MSL2-260C)					
Package Construction Details					
Assembly Site:	TI Taiwan	Mold Compound:	4206193		
# Pins-Designator, Family:	20-PW, TSSOP	Mount Compound:	4042500		
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.96 Mil Dia., Cu		
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results					
Reliability Test	Conditions	Pass / Fail			
		Lot 1	Lot2	Lot 3	
**High Temp. Storage Bake	170 (420 Hrs)	77/0	77/0	77/0	
**Autoclave 121C	121C, 2 atm (96 Hrs)	77/0	77/0	77/0	
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	77/0	77/0	
Manufacturability	(per mfg. Site specification)	Pass	Pass	Pass	

Qual Vehicle 6: TLC5930PWP (MSL2-260C)					
Package Construction Details					
Assembly Site:	TI Taiwan	Mold Compound:	4205443		
# Pins-Designator, Family:	24-PWP, HTSSOP	Mount Compound:	4042504		
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.96 Mil Dia., Cu		
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results					
Reliability Test	Conditions	Pass / Fail			
		Lot 1	Lot2	Lot 3	
**High Temp. Storage Bake	170C (420 Hrs)	77/0	77/0	77/0	
**Autoclave 121C	121C, 2 atm (96 Hrs)	77/0	77/0	77/0	
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	77/0	77/0	
Manufacturability	(per mfg. Site specification)	Pass	Pass	Pass	
Notes: **Tests require preconditioning sequence: MSL2-260C					

Qual Vehicle 7: TPS77701PWP (MSL2-260C)					
Package Construction Details					
Assembly Site:	TI Malaysia	Mold Compound:	4205443		
# Pins-Designator, Family:	20-PWP, HTSSOP	Mount Compound:	4042504		
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.96 Mil Dia., Cu		
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results					
Reliability Test	Conditions	Pass / Fail			
		Lot 1	Lot2	Lot 3	
**Thermal Shock	-65C/+150C (500 Cyc)	77/0	77/0	77/0	
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	77/0	77/0	
Manufacturability	(per mfg. Site specification)	Pass	Pass	Pass	
Notes: **Preconditioning sequence: MSL2-260C					

Qual Vehicle 8: TPS77801PWP (MSL2-260C)				
Package Construction Details				
Assembly Site:	TI Taiwan	Mold Compound:	4209002	
# Pins-Designator, Family:	20-PWP, HTSSOP	Mount Compound:	4042500	
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.96 Mil Dia., Cu	
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Pass / Fail		
		Lot 1	Lot2	Lot 3
**High Temp. Storage Bake	170C (420 Hrs)	77/0	77/0	77/0
**Autoclave 121C	121C, 2 atm (96 Hrs)	77/0	77/0	77/0
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	77/0	77/0
**Thermal Shock	-65C/+150C (500 Cyc)	77/0	77/0	77/0
Manufacturability	(per mfg. Site specification)	Pass	Pass	Pass
Notes: **Preconditioning sequence: MSL2-260C				

Reference Qualification 3 (TSSOP 1.3 mil Cu wire)

Qualification Data: Approved 02/13/2009

This qualification has been developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qualification Device(s) Construction Details:

Qual Vehicle 1: TAS5182DCA (MSL=LEVEL3-260C)

Package Construction Details

Assembly Site:	TI Taiwan	Mold Compound:	4205443	
# Pins-Designator, Family:	56-DCA, TSSOP	Mount Compound:	4206201	
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	1.3 Mil Dia. Cu	
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Sample Size (PASS/FAIL)		
		Lot#1	Lot#2	Lot#3
**Temp Cycle	-65/+150C, 500 cycles	77/0	-	-
**High Temp Storage Bake	170C, 420 Hrs	77/0	-	-
**Autoclave	121C, 2 atm 96 Hrs	77/0	-	-
**Thermal Shock	-65/150C, 1000 Cycles	77/0	-	-
Manufacturability (Assembly)	As per assembly site spec	Pass	-	-
** - Test requires Moisture Preconditioning				

Qual Vehicle 2: TPS40057PWP (MSL=LEVEL2-260C)**Package Construction Details**

Assembly Site:	TI Taiwan	Mold Compound:	4205443
# Pins-Designator, Family:	16-PWP, TSSOP	Mount Compound:	4042504
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	1.3 Mil Dia. Cu

Qualification: Plan Test Results

Reliability Test	Conditions	Sample Size (PASS/FAIL)		
		Lot#1	Lot#2	Lot#3
**Temp Cycle	-65/+150C, 500 cycles	77/0	-	-
**High Temp Storage Bake	170C, 420 Hrs	77/0	-	-
**Autoclave	121C, 2 atm 96 Hrs	77/0	-	-
**Thermal Shock	-65/150C, 1000 Cycles	77/0	-	-
Manufacturability (Assembly)	As per assembly site spec	Pass	-	-

** - Test requires Moisture Preconditioning

Qual Vehicle 3: TPS65161PWP (MSL=LEVEL2-260C)**Package Construction Details**

Assembly Site:	TI Taiwan	Mold Compound:	4205443
# Pins-Designator, Family:	28-PWP, TSSOP	Mount Compound:	4042504
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	1.3 Mil Dia. Cu

Qualification: Plan Test Results

Reliability Test	Conditions	Sample Size (PASS/FAIL)		
		Lot#1	Lot#2	Lot#3
**Temp Cycle	-65/+150C, 500 cycles	77/0	-	-
**High Temp Storage Bake	170C, 420 Hrs	77/0	-	-
**Autoclave	121C, 2 atm, 96 Hrs	77/0	-	-
**Thermal Shock	-65/150C, 1000 Cycles	77/0	-	-
Manufacturability (Assembly)	As per assembly site spec	Pass	-	-

** - Test requires Moisture Preconditioning

Qual Vehicle 4: UCC2891PW (MSL=LEVEL1-260C)**Package Construction Details**

Assembly Site:	TI Malaysia	Mold Compound:	4206193
# Pins-Designator, Family:	16-PW, TSSOP	Mount Compound:	4042500
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	1.3 Mil Dia. Cu

Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Sample Size (PASS/FAIL)		
		Lot#1	Lot#2	Lot#3
**Temp Cycle	-65/+150C, 500 cycles	77/0	-	-
**High Temp Storage Bake	170C, 420 Hrs	77/0	-	-
**Autoclave	121C, 2 atm, 96 Hrs	77/0	-	-
**Thermal Shock	-65/150C, 1000 Cycles	77/0	-	-
Manufacturability (Assembly)	As per assembly site spec	Pass	-	-
** - Test requires Moisture Preconditioning				

Qual Vehicle 5: UCC2897PW (MSL=LEVEL1-260C)				
Package Construction Details				
Assembly Site:	TI Malaysia	Mold Compound:	4206193	
# Pins-Designator, Family:	20-PW, TSSOP	Mount Compound:	4042500	
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	1.3 Mil Dia. Cu	
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Sample Size (PASS/FAIL)		
		Lot#1	Lot#2	Lot#3
**Temp Cycle	-65/+150C, 500 cycles	77/0	77/0	-
**High Temp Storage Bake	170C, 420 Hrs	77/0	77/0	-
**Autoclave	121C, 2 atm, 96 Hrs	77/0	77/0	-
**Thermal Shock	-65/150C, 1000 Cycles	77/0	77/0	-
Manufacturability (Assembly)	As per assembly site spec	Pass	Pass	-
** - Test requires Moisture Preconditioning				

Reference Qualification 4 (TSSOP 2.0 mil Cu wire)

Qualification Data: Approved 02/18/2009

This qualification has been developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.				
Qualification Device(s) Construction Details:				
Qual Vehicle : TPS2236DAP (MSL=LEVEL3-260C)				
Package Construction Details				
Assembly Site:	TI Taiwan	Mold Compound:	4205443	
# Pins-Designator, Family:	32-DAP, TSSOP	Mount Compound:	4042504	
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	2.0 Mil Dia. Cu	

Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Sample Size (PASS/FAIL)		
		Lot#1	Lot#2	Lot#3
**Temp Cycle	-65/+150C, 500 cycles	77/0	-	-
**High Temp Storage Bake	170C, 420 Hrs	77/0	-	-
**Autoclave	121C, 2 atm, 96 Hrs	77/0	-	-
**Thermal Shock	-65/150C, 1000 Cycles	77/0	-	-
Manufacturability (Assembly)	As per assembly site spec	Pass	-	-
** - Test requires Moisture Preconditioning				

Reference Qualification 5 (QFP 0.8 mil Cu wire)

Qualification Data: Approved 03/16/2010

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable specifications.				
Qual Vehicle : TSB43AB23PDT (MSL=LEVEL3-260C)				
Package Construction Details				
Assembly Site:	TI Philippines	Mold Compound:	4205442	
Pin Count, Package Family:	128, TQFP	Mount Compound:	4042504	
Lead Finish, Base	NiPdAu, Cu	Bond Wire:	0.8 Mil Dia. Cu	
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results: Approved 3/16/2010				
Reliability Test	Conditions	Sample Size (PASS/FAIL)		
		Lot#1	Lot#2	Lot#3
**High Temp. Storage Bake	170C (420 Hours)	77/0	77/0	77/0
**Autoclave	121C, 2 atm, 96 Hours	77/0	77/0	77/0
**T/C -65C/150C	-65C/+150C (500 Cycles)	77/0	77/0	77/0
**T/C -55C/125C	-55C/+125C (1000 Cycles)	77/0	77/0	77/0
Manufacturability (Assembly)	(per mfg. Site specification)	Pass	Pass	Pass
**Thermal Shock	-65C/+150C (500 Cycles)	77/0	77/0	77/0
Note** Test requires Moisture Preconditioning				

Qualification Data: Approved 07/07/2011

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable specifications.				
Qual Vehicle : TSB81BA3EPFP (MSL3-260C)				
Package Construction Details				
Assembly Site:	TI Taiwan	Mold Compound:	4205443	
# Pins-Designator, Family:	80-PFP, TQFP	Mount Compound:	4042504	
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.8 Mil Dia., Cu	

Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Pass / Fail		
		Lot 1	Lot2	Lot 3
**High Temp. Storage Bake	170C (420 Hrs)	77/0	77/0	77/0
**Autoclave 121C	121C, 2 atm (96 Hrs)	77/0	77/0	77/0
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	77/0	77/0
**Thermal Shock	-65C/+150C (500 Cyc)	77/0	77/0	77/0
Manufacturability	(per mfg. Site specification)	Pass	Pass	Pass
Notes: **Preconditioning sequence: MSL3-260C				

Reference Qualification 6 (QFP 0.96 mil Cu wire)

Qualification Data: Approved 03/16/2010

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable specifications.				
Qual Vehicle : TMS351PAG (MSL=LEVEL3-260C)				
Package Construction Details				
Assembly Site:	TI Philippines	Mold Compound:	4205442	
# Pins-Designator, Family:	64-PAG, TQFP	Mount Compound:	4042504	
Lead Finish, Base	NiPdAu, Cu	Bond Wire:	0.96 Mil Dia. Cu	
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results:				
Reliability Test	Conditions	Sample Size (PASS/FAIL)		
		Lot#1	Lot#2	Lot#3
**High Temp. Storage Bake	170C (420 Hours)	77/0	77/0	77/0
**Autoclave 121C	121C, 2 atm (96 Hours)	77/0	77/0	77/0
**T/C -65C/150C	-65C/+150°C (500 Cycles)	77/0	77/0	77/0
**T/C -55C/125C	-55C/+125C (1000 Cycles)	77/0	77/0	77/0
Manufacturability (Assembly)	(per mfg. Site specification)	Pass	Pass	Pass
**Thermal Shock	-65C/+150C (500 Cycles)	77/0	77/0	77/0
Note** Test requires Moisture Preconditioning				

Qualification Data: Approved 07/07/2011

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable specifications.				
Qual Vehicle 1: F741900APFB (MSL3-250C)				
Package Construction Details				
Assembly Site:	TI Taiwan	Mold Compound:	4205442	
# Pins-Designator, Family:	48-PFB, TQFP	Mount Compound:	4042504	
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.96 Mil Dia., Cu	

Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Pass / Fail		
		Lot 1	Lot2	Lot 3
**High Temp. Storage Bake	170C (420 Hrs)	77/0	77/0	77/0
**Autoclave 121C	121C, 2 atm (96 Hrs)	77/0	77/0	77/0
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	77/0	77/0
**Thermal Shock	-65C/+150C (500 Cyc)	77/0	77/0	77/0
Manufacturability	(per mfg. Site specification)	Pass	Pass	Pass
Notes: **Preconditioning sequence: MSL3-250C				

Qual Vehicle 2: THS7327PHP (MSL3-260C)				
Package Construction Details				
Assembly Site:	TI Taiwan	Mold Compound:	4205443	
# Pins-Designator, Family:	48-PHP, HTQFP	Mount Compound:	4042504	
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.96 Mil Dia., Cu	
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Pass / Fail		
		Lot 1	Lot2	Lot 3
**High Temp. Storage Bake	170C (420 Hrs)	77/0	-	-
**Autoclave 121C	121C, 2 atm (96 Hrs)	77/0	-	-
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	-	-
**Thermal Shock	-65C/+150C (500 Cyc)	77/0	-	-
Manufacturability	(per mfg. Site specification)	Pass	-	-
Notes: **Preconditioning sequence: MSL3-260C				

Qual Vehicle 3: TL16C550DPTR (MSL3-260C)				
Package Construction Details				
Assembly Site:	TI Taiwan	Mold Compound:	4205442	
# Pins-Designator, Family:	48-PT, LQFP	Mount Compound:	4042504	
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.96 Mil Dia., Cu	
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Pass / Fail		
		Lot 1	Lot2	Lot 3
**High Temp. Storage Bake	170C (420 Hrs)	77/0	-	-
**Autoclave 121C	121C, 2 atm (96 Hrs)	77/0	-	-
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	-	-
**Thermal Shock	-65C/+150C (500 Cyc)	77/0	-	-
Manufacturability	(per mfg. Site specification)	Pass	-	-
Notes: **Preconditioning sequence: MSL3-260C				

Qual Vehicle 4: TL16C752BPT (MSL3-260C)				
Package Construction Details				
Assembly Site:	TI Taiwan	Mold Compound:	4205442	
# Pins-Designator, Family:	48-PT, LQFP	Mount Compound:	4042504	
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.96 Mil Dia., Cu	
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Sample Size (PASS/FAIL)		
		Lot#1	Lot#2	Lot#3
**High Temp. Storage Bake	170C (420 Hrs)	77/0	-	-
**Autoclave 121C	121C, 2 atm (96 Hours)	77/0	-	-
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	-	-
**Thermal Shock	-65C/+150C (500 Cyc)	77/0	-	-
Manufacturability (Assembly)	(per mfg. Site specification)	Pass	-	-
Notes: **Tests require preconditioning sequence: MSL3-260C				
Qual Vehicle 5: TPS5130PTR (MSL1-260C)				
Package Construction Details				
Assembly Site:	TI Taiwan	Mold Compound:	4205442	
# Pins-Designator, Family:	48-PT, LQFP	Mount Compound:	4042504	
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.96 Mil Dia., Cu	
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Pass / Fail		
		Lot 1	Lot2	Lot 3
**High Temp. Storage Bake	170C (420 Hrs)	77/0	-	-
**Autoclave 121C	121C, 2 atm (96 Hrs)	77/0	-	-
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	-	-
**Thermal Shock	-65C/+150C (500 Cyc)	77/0	-	-
Manufacturability (Assembly)	(per mfg. Site specification)	Pass	-	-
Notes: **Tests require preconditioning sequence: MSL1-260C				

Qual Vehicle 6: TSB12LV21BPGF (MSL3-260C)				
Package Construction Details				
Assembly Site:	TI Philippines	Mold Compound:	4205442	
# Pins-Designator, Family:	176-PGF, LQFP	Mount Compound:	4042504	
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.96 Mil Dia., Cu	
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Pass / Fail		
		Lot 1	Lot2	Lot 3
**High Temp. Storage Bake	170C (420 Hrs)	77/0	77/0	77/0
**Autoclave 121C	121C, 2 atm (96 Hrs)	77/0	77/0	77/0
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	77/0	77/0
**Thermal Shock	-65C/+150C (500 Cyc)	77/0	77/0	77/0
Manufacturability	(per mfg. Site specification)	Pass	Pass	Pass
Notes: **Preconditioning sequence: MSL3-260C				

Qual Vehicle 7: TSB41AB1PHP (MSL3-260C)				
Package Construction Details				
Assembly Site:	TI Taiwan	Mold Compound:	4205443	
# Pins-Designator, Family:	48-PHP, HTQFP	Mount Compound:	4042504	
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.96 Mil Dia., Cu	
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Pass / Fail		
		Lot 1	Lot2	Lot 3
**Thermal Shock	-65C/+150C (500 Cyc)	77/0	77/0	-
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	77/0	-
Manufacturability	(per mfg. Site specification)	Pass	Pass	-
Notes: **Preconditioning sequence: MSL3-260C				

Qual Vehicle 8: UCC5696PN (MSL3-260C)				
Package Construction Details				
Assembly Site:	TI Taiwan	Mold Compound:	4205442	
# Pins-Designator, Family:	80-PN,LQFP	Mount Compound:	4042504	
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.96 Mil Dia., Cu	
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Pass / Fail		
		Lot 1	Lot2	Lot 3
**Thermal Shock	-65C/+150C (500 Cyc)	77/0	77/0	-
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	77/0	-
Manufacturability	(per mfg. Site specification)	Pass	Pass	-
Notes: **Preconditioning sequence: MSL3-260C				

Reference Qualification 7 (QFN 0.8 mil Cu wire)

Qualification Data: Approved 07/01/2011

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qual Vehicle : TLVDAC32IRHBR (MSL2-260C)				
Package Construction Details				
Assembly Site:	TI Clark	Mold Compound:	4208625	
# Pins-Designator, Family:	32-RHB, VQFN	Mount Compound:	4207768	
Solder Ball Composition:	NiPdAu, Cu	Bond Wire:	0.8 Mil Dia., Cu	
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Pass / Fail		
		Lot 1	Lot2	Lot 3
**High Temp. Storage Bake	170C (420 Hrs)	77/0	77/0	77/0
**Autoclave 121C	121C, 2 atm (96 Hrs)	77/0	77/0	77/0
*T/C -65C/150C	-65C/+150°C (500 Cycles)	77/0	77/0	77/0
Manufacturability	(per mfg. Site specification)	Pass	Pass	Pass
X-Ray	(top side only)	5/0	5/0	5/0
Notes: **Preconditioning sequence: MSL2-260C				

Reference Qualification 8 (QFN 0.96 mil Cu wire)

Qualification Data: Approved 01/03/2011

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.					
Qual Vehicle 1: BQ24703RHD (MSL2-260C)					
Package Construction Details					
Assembly Site:	TI Malaysia	Mold Compound:	4208625		
# Pins-Designator, Family:	28-RHD, VQFN	Mount Compound:	4205846		
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.96 Mil Dia., Cu		
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results					
Reliability Test	Conditions	Pass / Fail			
		Lot 1	Lot2	Lot 3	
**High Temp. Storage Bake	150C (500, 1000 Hrs)	77/0	77/0	77/0	
**Autoclave 121C	121C, 2 atm (96 Hrs)	77/0	77/0	77/0	
**T/C -65C/150C	-65C/+150C (500Cyc)	77/0	77/0	77/0	
Manufacturability	(per mfg. Site specification)	Pass	Pass	Pass	
Notes: **Tests require preconditioning sequence: MSL2-260C					
Qual Vehicle 2: SN75DP139RGZ (MSL3-260C)					
Package Construction Details					
Assembly Site:	TI Malaysia	Mold Compound:	4208625		
# Pins-Designator, Family:	48-RGZ, VQFN	Mount Compound:	4205846		
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.96 Mil Dia., Cu		
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results					
Reliability Test	Conditions	Pass / Fail			
		Lot 1	Lot2	Lot 3	
**High Temp. Storage Bake	150C (500, 1000 Hrs)	77/0	77/0	77/0	
**Autoclave 121C	121C, 2 atm (96 Hrs)	77/0	77/0	77/0	
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	77/0	77/0	
Manufacturability	(per mfg. Site specification)	Pass	Pass	Pass	
Notes: **Preconditioning sequence: MSL3-260C					
Qual Vehicle 3: TPA5050RSA (MSL2-260C)					
Package Construction Details					
Assembly Site:	TI Malaysia	Mold Compound:	4208625		
# Pins-Designator, Family:	16-RSA, VQFN	Mount Compound:	4205846		
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.96 Mil Dia., Cu		
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results					
Reliability Test	Conditions	Pass / Fail			
		Lot 1	Lot2	Lot 3	
**High Temp. Storage Bake	150C (500, 1000 Hrs)	77/0	77/0	77/0	
**Autoclave 121C	121C, 2 atm (96 Hrs)	77/0	77/0	77/0	
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	77/0	77/0	
Bond Strength	76 ball bonds, min. 3 units	76/0	76/0	76/0	
Manufacturability	(per mfg. Site specification)	Pass	Pass	Pass	
Notes: **Preconditioning sequence: MSL2-260C					

Qual Vehicle 4: TPS51427ARHB (MSL2-260C)**Package Construction Details**

Assembly Site:	TI Malaysia	Mold Compound:	4208625
# Pins-Designator, Family:	32-RHB, VQFN	Mount Compound:	4205846
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.96 Mil Dia., Cu

Qualification: Plan **Test Results**

Reliability Test	Conditions	Pass / Fail		
		Lot 1	Lot2	Lot 3
**High Temp. Storage Bake	150C (500, 1000 Hrs)	77/0	77/0	77/0
**Autoclave 121C	121C, 2 atm (96 Hrs)	77/0	77/0	77/0
*T/C -65C/150C	-65C/+150°C (500 Cycles)	77/0	77/0	77/0
Manufacturability	(per mfg. Site specification)	Pass	Pass	Pass

Notes: **Preconditioning sequence: MSL2-260C

Qual Vehicle 5: TPS51620RHAR (MSL2-260C)**Package Construction Details**

Assembly Site:	TI Malaysia	Mold Compound:	4208625
# Pins-Designator, Family:	40-RHA, VQFN	Mount Compound:	4205846
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.96 Mil Dia., Cu

Qualification: Plan **Test Results**

Reliability Test	Conditions	Pass / Fail		
		Lot 1	Lot2	Lot 3
**High Temp. Storage Bake	150C (500, 1000 Hrs)	77/0	77/0	77/0
**Autoclave 121C	121C, 2 atm (96 Hrs)	77/0	77/0	77/0
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	77/0	77/0
Bond Strength	76 ball bonds, min. 3 units	76/0	76/0	76/0
Manufacturability	(per mfg. Site specification)	Pass	Pass	Pass

Notes: **Preconditioning sequence: MSL2-260C

Qualification Data: Approved 07/01/2011

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qual Vehicle 1 : DRV401AIRGW (MSL 2-260C)**Package Construction Details**

Assembly Site:	TI Clark	Mold Compound:	4208625
# Pins-Designator, Family:	20-RGW,VQFN	Mount Compound:	4207768
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.96 Mil Dia., Cu

Qualification: Plan **Test Results**

Reliability Test	Conditions	Pass / Fail		
		Lot 1	Lot2	Lot 3
**High Temp. Storage Bake	170C (420 Hrs)	77/0	77/0	77/0
**Autoclave 121C	121C, 2 atm (96 Hrs)	77/0	77/0	77/0
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	77/0	77/0
Ball Bond Shear	76 balls, 3 units min	76/0	76/0	76/0
Bond Pull	76 Wire, 3 units min	76/0	76/0	76/0
Manufacturability	(per mfg. Site specification)	Pass	Pass	Pass
X-ray	(top side only)	5/0	5/0	5/0

Notes: **Preconditioning sequence: MSL2-260C

Qual Vehicle 2 : SN75DP122ARTQ (MSL3-260C)				
Package Construction Details				
Assembly Site:	TI Clark	Mold Compound:	4208625	
# Pins-Designator, Family:	56-RTQ, VQFN	Mount Compound:	4207768	
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.96 Mil Dia., Cu	
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Pass / Fail		
		Lot 1	Lot2	Lot 3
**High Temp. Storage Bake	170C (420 Hrs)	77/0	77/0	77/0
**Autoclave 121C	121C, 2 atm (96 Hrs)	77/0	77/0	77/0
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	77/0	77/0
Ball Bond Shear	76 balls 3 units min	76/0	76/0	76/0
Bond Pull	76 Wire 3 units min	76/0	76/0	76/0
Manufacturability	(per mfg. Site specification)	Pass	Pass	Pass
X-ray	(top side only)	5/0	5/0	5/0
Notes: **Preconditioning sequence: MSL3-260C				
Qual Vehicle 3 : TPA2005D1DRB (MSL 2-260C)				
Package Construction Details				
Assembly Site:	TI Clark	Mold Compound:	4208625	
# Pins-Designator, Family:	8-DRB, VSON	Mount Compound:	4207768	
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.96 Mil Dia., Cu	
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Pass / Fail		
		Lot 1	Lot2	Lot 3
**High Temp. Storage Bake	170C (420 Hrs)	77/0	77/0	77/0
**Autoclave 121C	121C, 2 atm (96 Hrs)	77/0	77/0	77/0
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	77/0	77/0
Ball Bond Shear	76 balls 3 units min	76/0	76/0	76/0
Bond Pull	76 Wire 3 units min	76/0	76/0	76/0
Manufacturability	(per mfg. Site specification)	Pass	Pass	Pass
X-ray	(top side only)	5/0	5/0	5/0
Notes: **Preconditioning sequence: Level 2-260C				
Qual Vehicle 4 : TPS51217DSCR_RFAB (MSL2-260C)				
Package Construction Details				
Assembly Site:	TI Clark	Mold Compound:	4208625	
# Pins-Designator, Family:	10-DSC, WSON	Mount Compound:	4207768	
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.96 Mil Dia., Cu	

Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Pass / Fail		
		Lot 1	Lot2	Lot 3
High Temp Operating Life	125C (1000 Hrs), Vddmax	77/0	77/0	77/0
**High Temp. Storage Bake	170C (420 Hrs)	77/0	77/0	77/0
**Biased HAST	130C/85%RH (96 Hrs)	77/0	77/0	77/0
**Autoclave 121C	121C, 2 atm (96 Hrs)	77/0	77/0	77/0
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	77/0	77/0
Ball Bond Shear	76 balls, 3 units min	76/0	76/0	76/0
Bond Pull	76 Wires, 3 units min	76/0	76/0	76/0
Manufacturability	(per mfg. Site specification)	Pass	Pass	Pass
X-ray	(top side only)	5/0	5/0	5/0
Notes: **Preconditioning sequence: Level 2-260C				
Qual Vehicle 5 : TPS51217DSC_UMC (MSL2-260C)				
Package Construction Details				
Assembly Site:	TI Clark	Mold Compound:	4208625	
# Pins-Designator, Family:	10-DSC, WSON	Mount Compound:	4207768	
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.96 Mil Dia., Cu	
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Pass / Fail		
		Lot 1	Lot2	Lot 3
**High Temp. Storage Bake	170C (420 Hrs)	77/0	77/0	77/0
**Autoclave 121C	121C, 2 atm (96 Hrs)	77/0	77/0	77/0
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	77/0	77/0
Ball Bond Shear	76 balls, 3 units min	76/0	76/0	76/0
Bond Pull	76 Wires, 3 units min	76/0	76/0	76/0
Manufacturability	(per mfg. Site specification)	Pass	Pass	Pass
X-ray	(top side only)	5/0	5/0	5/0
Notes: **Preconditioning sequence: MSL2-260C				

Qualification Data: Approved 06/02/2009

This qualification has been developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.				
Qualification Device(s) Construction Details:				
Qual Vehicle 1: TPA6132A2RTE (MSL=LEVEL2-260C)				
Package Construction Details				
Assembly Site:	TI Malaysia	Mold Compound:	4208625-0004	
# Pins-Designator, Family:	16-RTE, WQFN	Mount Compound:	4205846-0001	
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.96 Mil Dia. Cu	

Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Sample Size (PASS/FAIL)		
		Lot#1	Lot#2	Lot#3
Temp Cycle*	-65/+150C, 500 cycles	77/0	-	-
High Temp Storage Bake	+170C, 420 Hrs.	77/0	-	-
Autoclave*	+121C, 2 atm (96 Hrs)	77/0	-	-
Thermal Shock*	-65/150C, 1000 Cycles	77/0	-	-
Manufacturability (Assembly)	As per assembly site spec	Pass	-	-
* - Test requires Moisture Preconditioning				
Qual Vehicle 2: TPS51117RGY (MSL=LEVEL2-260C)				
Package Construction Details				
Assembly Site:	TI Malaysia	Mold Compound:	4208625-0004	
# Pins-Designator, Family:	14-RGY, VQFN	Mount Compound:	4205846-0001	
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.96 Mil Dia. Cu	
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Sample Size (PASS/FAIL)		
		Lot#1	Lot#2	Lot#3
Temp Cycle*	-65/+150C, 500 cycles	77/0	-	-
High Temp Storage Bake	+170C, 420 Hrs.	77/0	-	-
Autoclave*	+121C, 2 atm (96 Hrs)	77/0	-	-
Thermal Shock*	-65/150C, 1000 Cycles	77/0	-	-
Manufacturability (Assembly)	As per assembly site spec	Pass	-	-
* - Test requires Moisture Preconditioning				
Qual Vehicle 3: TPS51125RGE (MSL=LEVEL2-260C)				
Package Construction Details				
Assembly Site:	TI Malaysia	Mold Compound:	4208625-0004	
# Pins-Designator, Family:	24-RGE, VQFN	Mount Compound:	4205846-0001	
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.96 Mil Dia. Cu	
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Sample Size (PASS/FAIL)		
		Lot#1	Lot#2	Lot#3
Temp Cycle*	-65/+150C, 500 cycles	77/0	-	-
High Temp Storage Bake	+170C, 420 Hrs.	77/0	-	-
Autoclave*	+121C, 2 atm (96 Hrs)	77/0	-	-
Thermal Shock*	-65/150C, 1000 Cycles	77/0	-	-
Manufacturability (Assembly)	As per assembly site spec	Pass	-	-
* - Test requires Moisture Preconditioning				

Qual Vehicle 4: TPS51200DRC (MSL=LEVEL3-260C)				
Package Construction Details				
Assembly Site:	TI Malaysia	Mold Compound:	4208625-0004	
# Pins-Designator, Family:	10-DRC, VSON	Mount Compound:	4205846-0001	
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.96 Mil Dia. Cu	
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Sample Size (PASS/FAIL)		
		Lot#1	Lot#2	Lot#3
Temp Cycle*	-65/+150C, 500 cycles	77/0	-	-
High Temp Storage Bake	+170C, 420 Hrs.	77/0	-	-
Autoclave*	+121C, 2 atm (96 Hrs)	77/0	-	-
Thermal Shock*	-65/150C, 1000 Cycles	77/0	-	-
Manufacturability (Assembly)	As per assembly site spec	Pass	-	-
* - Test requires Moisture Preconditioning				

Reference Qualification 9 (QFN 1.3 mil Cu wire)

Qualification Data: Approved 02/02/2009

This qualification has been developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qualification Device(s) Construction Details:

Qual Vehicle 1: SN0701013DRC (MSL=LEVEL2-260C)				
Package Construction Details				
Assembly Site:	TI Malaysia	Mold Compound:	4208625-0001	
# Pins-Designator, Family:	10-DRC, VSON	Mount Compound:	4205846-0001	
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	1.3 Mil Dia. Cu	
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Sample Size (PASS/FAIL)		
		Lot#1	Lot#2	Lot#3
Temp Cycle*	-65/+150C, 500 cycles	77/0	77/0	77/0
High Temp Storage Bake	+170C, 420 Hrs.	77/0	77/0	77/0
Autoclave*	+121C, 2 atm (96 Hrs)	77/0	77/0	77/0
Thermal Shock*	-65/150C, 1000 Cycles	77/0	77/0	77/0
Manufacturability (Assembly)	As per assembly site spec	Pass	Pass	Pass
* - Test requires Moisture Preconditioning				
Qual Vehicle 2: TPA6040A4RHB (MSL=LEVEL3-260C)				
Package Construction Details				
Assembly Site:	TI Malaysia	Mold Compound:	4208625-0001	
# Pins-Designator, Family:	32-RHB, VQFN	Mount Compound:	4205846-0001	
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	1.3 Mil Dia. Cu	

Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Sample Size (PASS/FAIL)		
		Lot#1	Lot#2	Lot#3
Temp Cycle*	-65/+150C, 500 cycles	77/0	77/0	77/0
High Temp Storage Bake	+170C, 420 Hrs.	77/0	77/0	77/0
Autoclave*	+121C, 2 atm (96 Hrs)	77/0	77/0	77/0
Thermal Shock*	-65/150C, 1000 Cycles	77/0	77/0	77/0
Manufacturability (Assembly)	As per assembly site spec	Pass	Pass	Pass

* - Test requires Moisture Preconditioning

Reference Qualification 10 (QFN 2.0 mil Cu wire)

Qualification Data: Approved 1/26/2009

This qualification has been developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.			
Qualification Device(s) Construction Details:			
Qual Vehicle 1: TPA3100D2RGZ (2 die side by side multi-chip module) (MSL=LEVEL2-260C)			
Package Construction Details			
Assembly Site:	TI Malaysia	Mold Compound:	4208625
# Pins-Designator, Family:	48-RGZ, VQFN	Mount Compound:	4205846
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	2 Mil Dia. Cu (both die)
		Interchip Bonds:	Yes - 14
Qual Vehicle 2: TPS65136RTE (MSL=LEVEL2-260C)			
Package Construction Details			
Assembly Site:	TI Malaysia	Mold Compound:	4208625
# Pins-Designator, Family:	16-RTE, WQFN	Mount Compound:	4207768
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	2 Mil Dia. Cu

Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Sample Size (PASS/FAIL)		
		Lot#1	Lot#2	Lot#3
Temp Cycle*	-65/+150C, 500 cycles	77/0	-	-
High Temp Storage Bake	+170C, 420 Hrs.	77/0	-	-
Autoclave*	+121C, 2 atm (96 Hrs)	77/0	-	-
Thermal Shock*	-65/150C, 1000 Cycles	77/0	-	-
Manufacturability (Assembly)	As per assembly site spec	Pass	-	-

* - Test requires Moisture Preconditioning

Reference Qualification 11 (BGA 0.8 mil Cu wire)

Qualification Data: Approved 01/03/2011

This qualification has been developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.				
Qualification Device(s) Construction Details:				
Qual Vehicle 1: TLV320AIC3106IZQE (MSL=LEVEL3-260C)				
Package Construction Details				
Assembly Site:	TI Taiwan	Mold Compound:	4205867	
# Pins-Designator, Family:	80-ZQE, JrBGA	Mount Compound:	4111062	
Solder Ball Diameter	11.81 mils	Bond Wire:	0.8 Mil Dia. Cu	
Solder Ball Composition	SnAgCu	Substrate Finish	Thin NiAu Ball Side	
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Sample Size (PASS/FAIL)		
		Lot#1	Lot#2	Lot#3
*High Temp. Storage Bake	150C 1000 Hours	77/0	77/0	77/0
*Autoclave 121C	121C, 2 atm 96 Hours	77/0	77/0	77/0
*Unbiased HAST	130C/85%RH 96 Hours	77/0	77/0	77/0
*Temperature Cycle	-55C/+125C 1000 Cycles	77/0	77/0	77/0
Manufacturability	per mfg. Site specification	Pass	Pass	Pass
* Preconditioning Required L3-260C				

Qual Vehicle 2: VSP6822AZRC (MSL=LEVEL3-260C)				
Package Construction Details				
Assembly Site:	TI Taiwan	Mold Compound:	4205867	
# Pins-Designator, Family:	98-ZRC, JrBGA	Mount Compound:	4111062	
Solder Ball Diameter	11.81 mils	Bond Wire:	0.8 Mil Dia. Cu	
Solder Ball Composition	SnAgCu	Substrate Finish	CuNiAu Ball Side	
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Sample Size (PASS/FAIL)		
		Lot#1	Lot#2	Lot#3
*High Temp. Storage Bake	150C 1000 Hours	77/0	77/0	77/0
*Autoclave 121C	121C, 2 atm 96 Hours	77/0	77/0	77/0
*Unbiased HAST	130C/85%RH 96 Hours	77/0	77/0	77/0
*Temperature Cycle	-55C/+125C 1000 Cycles	77/0	77/0	77/0
Manufacturability	per mfg. Site specification	Pass	Pass	Pass
* Preconditioning Required L3-260C				

Qual Vehicle 3: VSP6825AZRC (MSL 3-260C)				
Package Construction Details				
Assembly Site:	TI Taiwan	Mold Compound:	4205867	
# Pins-Designator, Family:	103-ZRC, JrBGA	Mount Compound:	4111062	
Solder Ball Composition:	SnAgCu	Bond Wire:	0.8 Mil Dia., Cu	
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Pass / Fail		
		Lot 1	Lot2	Lot 3
**Biased HAST	130C/85%RH (96 Hrs)	77/0	77/0	77/0
Notes: **Test requires preconditioning sequence: MSL3-260C				

Qualification Data: Approved 07/07/2011

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.				
Qual Vehicle 1: TVAIC3106IZQER (MSL3-260C)				
Package Construction Details				
Assembly Site:	TI Philippines	Mold Compound:	4205867	
# Pins-Designator, Family:	80-ZQE, JrBGA	Mount Compound:	4111062	
Solder Ball Composition:	SnAgCu	Bond Wire:	0.8 Mil Dia., Cu	
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Pass / Fail		
		Lot 1	Lot2	Lot 3
**High Temp. Storage Bake	150C (500, 1000 Hrs)	77/0	77/0	77/0
**Autoclave 121C	121C, 2 atm (96 Hrs)	77/0	77/0	77/0
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	77/0	77/0
Bond Strength	76 ball bonds, min. 3 units	76/0	76/0	76/0
Manufacturability	(per mfg. Site specification)	Pass	Pass	Pass
Notes: **Preconditioning sequence: MSL3-260C				

Qual Vehicle 2: VSP6825AZRCR (MSL3-260C)				
Package Construction Details				
Assembly Site:	TI Taiwan	Mold Compound:	4205867	
# Pins-Designator, Family:	103-ZRC, JrBGA	Mount Compound:	4111062	
Solder Ball Composition:	SnAgCu	Bond Wire:	0.8 Mil Dia., Cu	
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Pass / Fail		
		Lot 1	Lot2	Lot 3
**High Temp. Storage Bake	150C (500, 1000 Hrs)	77/0	77/0	77/0
**Autoclave 121C	121C, 2 atm (96 Hrs)	77/0	77/0	77/0
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	77/0	77/0
Bond Strength	76 ball bonds, min. 3 units	76/0	76/0	76/0
Manufacturability	(per mfg. Site specification)	Pass	Pass	Pass
Notes: **Preconditioning sequence: MSL3-260C				

Qualification Data: Approved 03/16/2009

This qualification has been developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.				
Qualification Device(s) Construction Details:				
Qual Vehicle : TSB43DA42GHC (MSL=LEVEL3-220C)				
Package Construction Details				
Assembly Site:	TI Philippines	Mold Compound:	4203565	
# Pins-Designator, Family	169-GHC, UBGA	Mount Compound:	4073505	
Solder Ball Composition	SnPb	Bond Wire:	0.8 Mil Dia., Cu	
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Sample Size (PASS/FAIL)		
		Lot#1	Lot#2	Lot#3
*High Temp. Storage Bake	150C (1000 Hours)	77/0	77/0	77/0
*Unbiased HAST	130C/85%RH/33.3 psia (96 Hours)	77/0	77/0	77/0
T/C	-55C/+125C (1000 Cycles)	77/0	77/0	77/0
Manufacturability (Assembly)	(per mfg. Site specification)	Pass	Pass	Pass
Note* Test requires Moisture Preconditioning				

Reference Qualification 12 (BGA 0.96 mil Cu wire)

Qualification Data: Approved 07/07/2011

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.				
Qual Vehicle 1: DRV590GQC (MSL2A-235C)				
Package Construction Details				
Assembly Site:	TI Taiwan	Mold Compound:	4205867	
# Pins-Designator, Family:	48-GQC, JRBGA	Mount Compound:	4111062	
Solder Ball Composition:	SnPb	Bond Wire:	0.96 Mil Dia., Cu	
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Pass / Fail		
		Lot 1	Lot2	Lot 3
**High Temp. Storage Bake	150C (500, 1000 Hrs)	77/0	77/0	77/0
**Autoclave 121C	121C, 2 atm (96 Hrs)	77/0	77/0	77/0
*T/C -65C/150C	-65C/+150°C (500 Cycles)	77/0	77/0	77/0
Manufacturability	(per mfg. Site specification)	Pass	Pass	Pass
Notes: **Preconditioning sequence: MSL2A-235C				

Qualification Data: Approved 08/25/2011

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qual Vehicle 1: TPS658621CZGU (MSL 3-260C)

Package Construction Details

Assembly Site:	TI Philippines	Mold Compound:	4203565
# Pins-Designator, Family:	169-ZGU, u*BGA	Mount Compound:	4111062
Solder Ball Composition:	SnAgCu	Bond Wire:	0.96 Mil Dia., Cu

Qualification: Plan Test Results

Reliability Test	Conditions	Sample Size
		Pass / Fail
**High Temp. Storage Bake	170C (420 Hrs)	77/0
**Unbiased HAST	130C/85%RH (96 Hrs)	77/0
**T/C -55C/125C	-55C/+125C (1000 Cyc)	77/0
Manufacturability	(per mfg. Site specification)	Pass

Notes: **Preconditioning sequence: Level 3-260C

Reference Qualification 13 (PDIP 0.96 mil Cu wire)

Qualification Data: Approved 09/27/2011

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qual Device 1: CD4072BE

Package Attributes:

Assembly Site:	TI Mexico	Mold Compound:	4042503
# Pins-Designator, Family:	14-N, PDIP	Mount Compound:	4147858
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.96 Mil Dia., Cu

Qualification: Plan Test Results

Reliability Test	Conditions	Sample Size
		Pass / Fail
Bond Strength	76 ball bonds, min. 3 units	76/0
Biased HAST	130C/85%RH (96 Hrs)	77/0
Autoclave 121C	121C, 2 ATM (96 hrs)	77/0
X-Ray	Topside Only	5/0
Manufacturability	(per mfg. Site specification)	Pass
Life test (High Temperature Operating Life)	150C (300 Hrs)	76/0
High Temp. Storage Bake	170C (420 Hrs)	77/0
T/C -65C/150C	-65C/+150C (500 Cyc)	77/0
Electrical Characterization	-	Pass
Thermal Shock	-65C/+150C (500 Cyc)	77/0

Qual Device 2: NE5532P		
Package Attributes:		
Assembly Site:	TI Mexico	Mold Compound: 4042503
# Pins-Designator, Family:	8-P, PDIP	Mount Compound: 4147858
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire: 0.96 Mil Dia., Cu
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results		
Reliability Test	Conditions	Sample Size Pass / Fail
Bond Strength	76 ball bonds, min. 3 units	76/0
Biased HAST	130C/85%RH (96 Hrs)	77/0
Autoclave 121C	121C, 2 ATM (96 hrs)	77/0
Thermal Shock	-65C/+150C (500 Cyc)	77/0
Manufacturability	(per mfg. Site specification)	Pass
Life test (High Temperature Operating Life)	150C (300 Hrs)	77/0
High Temp. Storage Bake	170C (420 Hrs)	77/0
Electrical Characterization	-	Pass
X-Ray	Topside Only	5/0
T/C -65C/150C	-65C/+150C (500 Cyc)	77/0
Qual Device 3: ULN2003AN		
Package Attributes:		
Assembly Site:	TI Mexico	Mold Compound: 4042503
# Pins-Designator, Family:	16-N, PDIP	Mount Compound: 4147858
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire: 0.96 Mil Dia., Cu
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results		
Reliability Test	Conditions	Sample Size Pass / Fail
Bond Strength	76 ball bonds, min. 3 units	76/0
Biased HAST	130C/85%RH (96 Hrs)	77/0
Autoclave 121C	121C, 2 ATM (96 hrs)	77/0
T/C -65C/150C	-65C/+150C (500 Cyc)	77/0
High Temp. Storage Bake	170C (420 Hrs)	77/0
Thermal Shock	-65C/+150C (500 Cyc)	77/0
Manufacturability	(per mfg. Site specification)	Pass
Life test (High Temperature Operating Life)	150C (300 Hrs)	77/0
Electrical Characterization	-	Pass
X-Ray	Topside Only	5/0

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com